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COLOR MONITOR SERVICE MANUAL

CHASSIS NO. : CA-138

MODEL: 505E (**505EM-KL***L***)

CAUTION
BEFORE SERVICING THE UNIT,
READ THE SAFETY PRECAUTIONS IN THIS MANUAL.



() **Same model for Service

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SPECIFICATIONS

1. PICTURE TUBE

Size	: 15 inch (Flat Square Tube)
Deflection Angle	: 90°
Neck Diameter	: 29.4 mm
Dot Pitch	: 0.28 mm
Face Treatment	: AR-ASC (Anti-Reflection and Anti-Static Coating) AG(Anti-Glare)
Low Radiation	: MPR-II, NON MPR II

2. SIGNAL

2-1. Horizontal & Vertical Sync

- 1) Input Voltage Level : Low= 0~1.2V, High= 2.5~5.5V
- 2) Sync Polarity : Positive or Negative

2-2. Video Input Signal

- 1) Voltage Level : 0 ~ 0.7 Vp-p
- a) Color 0, 0 : 0 Vp-p
- b) Color 7, 0 : 0.467 Vp-p
- c) Color 15, 0 : 0.7 Vp-p
- 2) Input Impedance : 75 Ω
- 3) Video Color : R, G, B Analog
- 4) Signal Format : Refer to the Timing Chart

2-3. Signal Connector

15-pin D-Sub Connector (Attached Type)

2-4. Scanning Frequency

- Horizontal : 30 ~ 54 kHz
- Vertical : 50 ~ 120 Hz

3. POWER SUPPLY

3-1. Power Range

AC 100~240V (Free Voltage), 50/60Hz, 1.0A Max.

3-2. Power Consumption

MODE	POWER CONSUMPTION	LED COLOR
MAX	75 W	GREEN
NORMAL (ON)	63 W	GREEN
STAND-BY	less than 15 W	FLASH
SUSPEND		
OFF	less than 5 W	FLASH

4. DISPLAY AREA

- 4-1. Active Video Area :
 - 285 x 215 mm (11.22" x 8.46") - Max Image Size
 - 270 x 200 mm (10.63" x 7.87") - Preset Image Size
- 4-2. Display Color : Full Colors
- 4-3. Display Resolution : 1024 x 768 / 60Hz
(Non-Interlace)
- 4-4. Video Bandwidth : 65 MHz

5. ENVIRONMENT

- 5-1. Operating Temperature: 10°C ~ 40°C
(Ambient)
- 5-2. Relative Humidity : 10%~ 80%
(Non-condensing)
- 5-3. Altitude : 3,000 m

6. DIMENSIONS (with TILT/SWIVEL)

- Width : 356.0 mm (14.01")
- Depth : 360.0 mm (13.10")
- Height : 371.0 mm (14.61")

7. WEIGHT (with TILT/SWIVEL)

- Net Weight : 12.5 kg (25.36 lbs)
- Gross Weight : 13.7 kg (30.21 lbs)

SAFETY PRECAUTIONS

SAFETY-RELATED COMPONENT WARNING!

There are special components used in this color monitor which are important for safety. **These parts are marked on the schematic diagram and the replacement parts list.** It is essential that these critical parts should be replaced with the manufacturer's specified parts to prevent X-radiation, shock, fire, or other hazards. Do not modify the original design without obtaining written permission from manufacturer or you will void the original parts and labor guarantee.

CAUTION: No modification of any circuit should be attempted.

Service work should be performed only after you are thoroughly familiar with all of the following safety checks and servicing guidelines.

SAFETY CHECK

Care should be taken while servicing this color monitor because of the high voltage used in the deflection circuits. These voltages are exposed in such areas as the associated flyback and yoke circuits.

FIRE & SHOCK HAZARD

An isolation transformer must be inserted between the color monitor and AC power line before servicing the chassis.

- In servicing, attention must be paid to the original lead dress specially in the high voltage circuit. If a short circuit is found, replace all parts which have been overheated as a result of the short circuit.
- All the protective devices must be reinstalled per the original design.
- Soldering must be inspected for the cold solder joints, frayed leads, damaged insulation, solder splashes, or the sharp points. Be sure to remove all foreign materials.

IMPLOSION PROTECTION

All used display tubes are equipped with an integral implosion protection system, but care should be taken to avoid damage and scratching during installation. Use only same type display tubes.

X-RADIATION

The only potential source of X-radiation is the picture tube. However, when the high voltage circuitry is operating properly there is no possibility of an X-radiation problem. The basic precaution which must be exercised is keep the high voltage at the factory recommended level; the normal high voltage is about 24.5kV. The following steps describe how to measure the high voltage and how to prevent X-radiation.

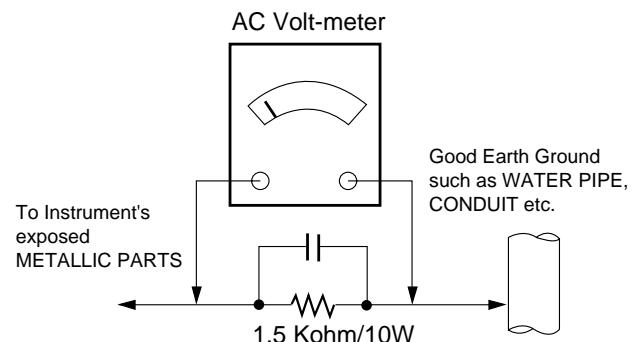
Note : It is important to use an accurate high voltage meter calibrated periodically.

- To measure the high voltage, use a high impedance high voltage meter, connect (-) to chassis and (+) to the CDT anode cap.
- Set the brightness control to maximum point at full white pattern.
- Measure the high voltage. The high voltage meter should be indicated at the factory recommended level.
- If the meter indication exceeds the maximum level, immediate service is required to prevent the possibility of premature component failure.
- To prevent X-radiation possibility, it is essential to use the specified picture tube.

CAUTION:

Please use only a plastic screwdriver to protect yourself from shock hazard during service operation.

Leakage Current Hot Check Circuit



SERVICING PRECAUTIONS

CAUTION: Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the **SAFETY PRECAUTIONS** on page 3 of this publication.

NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before;
 - a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
 - b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
 - c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.
- CAUTION:** A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.
- d. Discharging the picture tube anode.
2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe.
Do not test high voltage by "drawing an arc".
3. Discharge the picture tube anode only by (a) first connecting one end of an insulated clip lead to the degaussing or kine aquadag grounding system shield at the point where the picture tube socket ground lead is connected, and then (b) touch the other end of the insulated clip lead to the picture tube anode button, using an insulating handle to avoid personal contact with high voltage.
4. Do not spray chemicals on or near this receiver or any of its assemblies.
5. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10% (by volume) Acetone and 90% (by volume) isopropyl alcohol (90%-99% strength)
CAUTION: This is a flammable mixture.
Unless specified otherwise in this service manual, lubrication of contacts is not required.
6. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.
7. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.
8. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.
Always remove the test receiver ground lead last.

9. Use with this receiver only the test fixtures specified in this service manual.

CAUTION: Do not connect the test fixture ground strap to any heat sink in this receiver.

Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called *Electrostatically Sensitive (ES) Devices*. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the unit under test.
2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.
CAUTION: Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.
8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range of 500°F to 600°F.
2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
3. Keep the soldering iron tip clean and well tinned.
4. Thoroughly clean the surfaces to be soldered. Use a small wire-bristle (0.5 inch, or 1.25cm) brush with a metal handle.
Do not use freon-propelled spray-on cleaners.
5. Use the following unsoldering technique
 - a. Allow the soldering iron tip to reach normal temperature.
(500°F to 600°F)
 - b. Heat the component lead until the solder melts.
 - c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.
- CAUTION:** Work quickly to avoid overheating the circuitboard printed foil.
6. Use the following soldering technique.
 - a. Allow the soldering iron tip to reach a normal temperature (500°F to 600°F)
 - b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.
 - c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.
- CAUTION:** Work quickly to avoid overheating the circuit board printed foil.
- d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

IC Remove/Replacement

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

Removal

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

Replacement

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush. (It is not necessary to reapply acrylic coating to the areas).

"Small-Signal" Discrete Transistor

Removal/Replacement

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

Power Output, Transistor Device

Removal/Replacement

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

Diode Removal/Replacement

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

Fuse and Conventional Resistor

Removal/Replacement

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.

CAUTION: Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

Circuit Board Foil Repair

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

At IC Connections

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

At Other Connections

Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

1. Remove the defective copper pattern with a sharp knife.

Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.

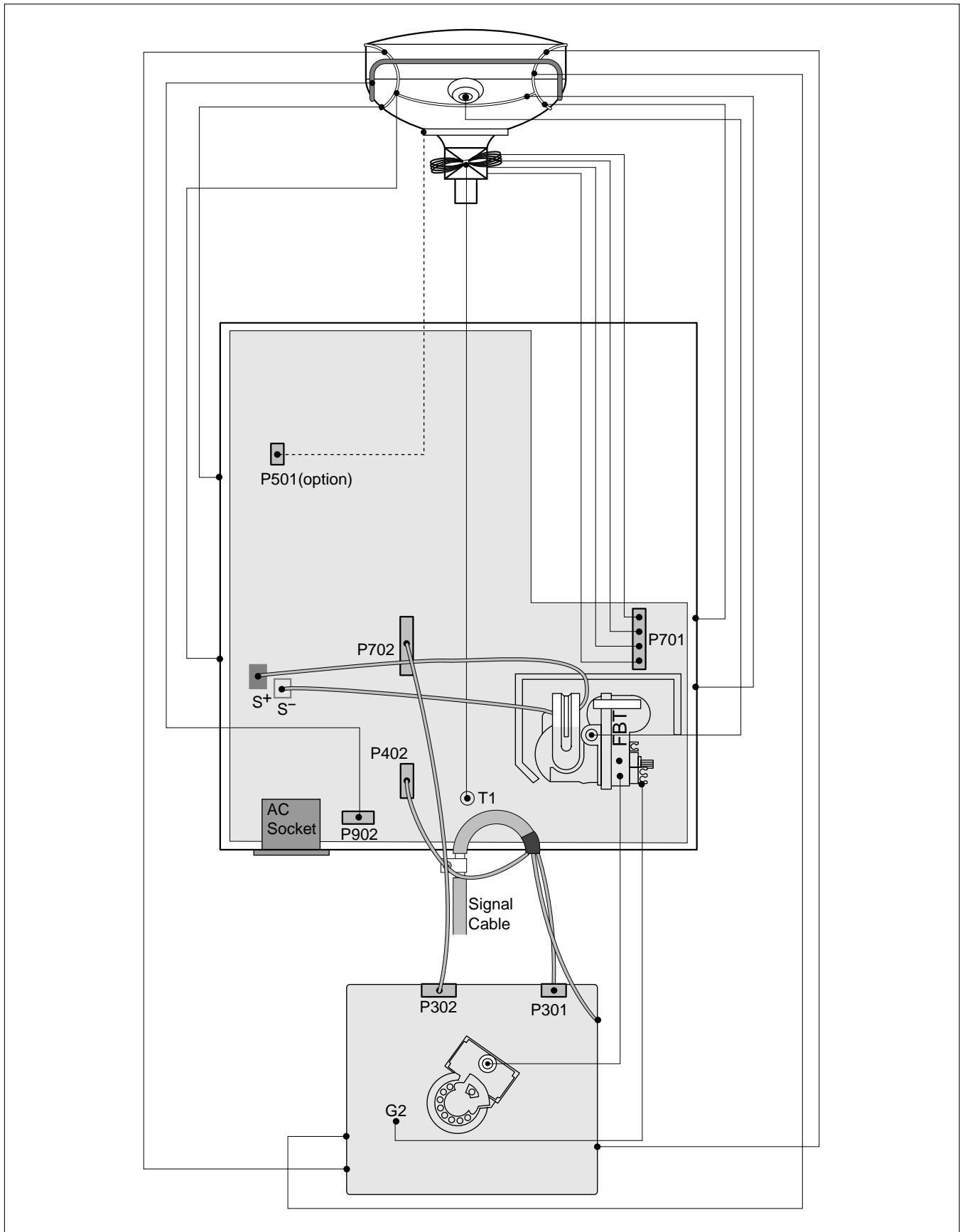
2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.

3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side.

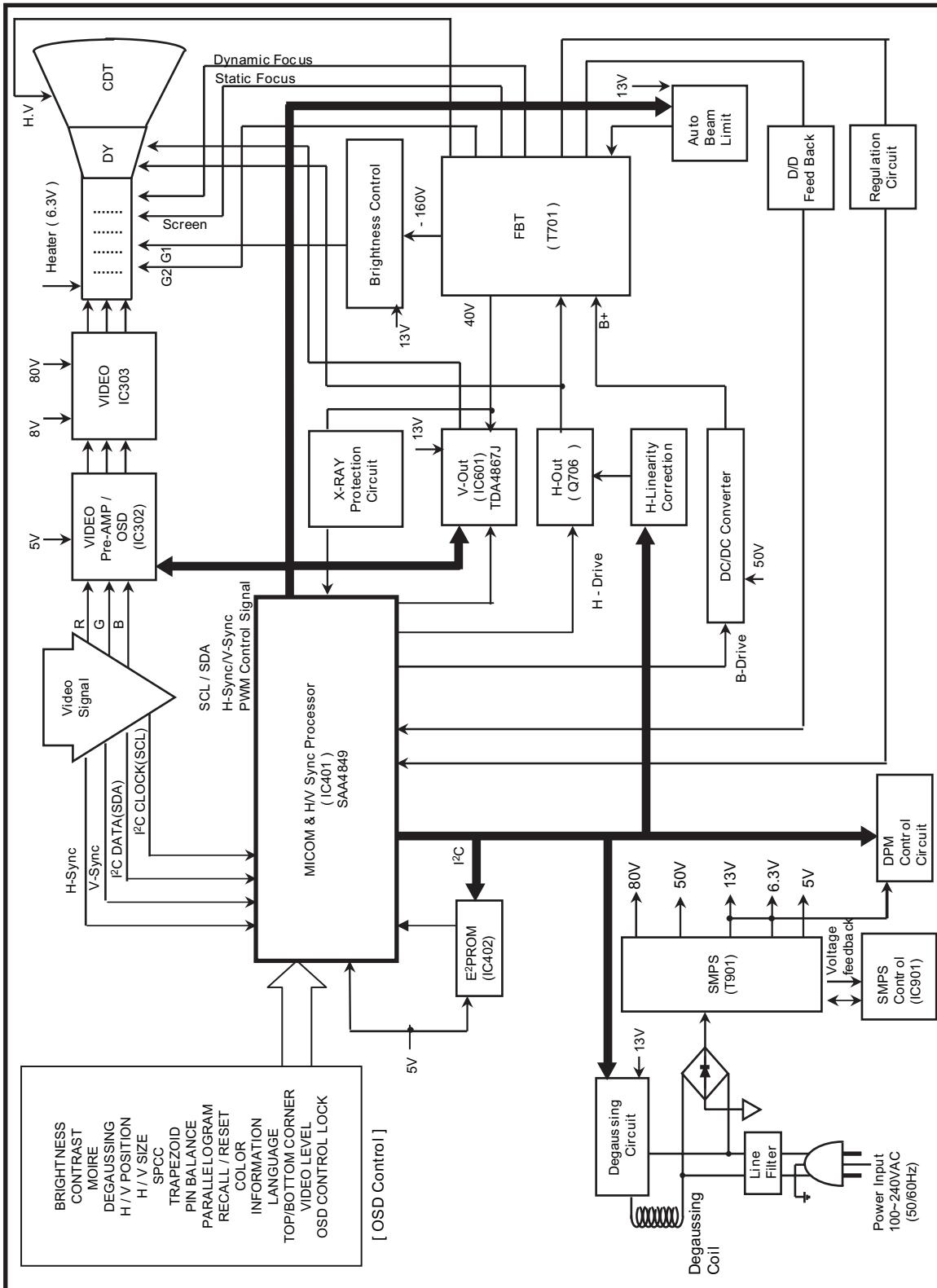
Carefully crimp and solder the connections.

CAUTION: Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

WIRING DIAGRAM



BLOCK DIAGRAM



DESCRIPTION OF BLOCK DIAGRAM

1. SMPS(Switching Mode Power Supply)

When you turn on the power switch, the operating procedure is as follows:

- 1) The AC line voltage is rectified by the bridge diode D900.
- 2) The control IC(IC901) starts switching and generates switch pulse in the primary turn of the SMPS transformer(T901)
- 3) The switching pulses of the primary turns are induced to the secondary turns of the transformer by the turn ratio. This pulses are rectified by each diode(D971, D961(D962),D951,D942,D941)
- 4) Each rectified DC voltage(80V, 50V, 13V, 6.3V and 5V)

2. Over Voltage Protection Circuit

When the input of IC901 Vin (pin 4) is more than 22V, all the secondary voltages of the SMPS transformer (T901) down to low value

3. Display Power Management Circuit(DPM)

1) STAND-BY & SUSPEND Mode

When no input of horizontal or vertical sync Q951, Q941 are turned off and Q952,Q942 are turned off. Then input power consumption is below 5 watts.

2) OFF Mode

When no input of horizontal and vertical sync Q951, Q941 are turned off and Q952, Q942 are turned off. Then input power consumption is below 5 watts.

4. Microprocessor Control & Horizontal and Vertical Sync Processor Circuit

The operating procedure is as follows ;

- 1) There is Horizontal & Vertical process function in Microprocessor.(IC401)
- 2) Microprocessor (IC401) discriminates the operating mode from the sync polarity and resolution.
- 3) After microprocessor reads these adjusted mode data stored at EEPROM, it controls operating mode data through IIC
- 4) Users can control screen condition by the OSD Select, Up, Down, Left, Right, Exit.
- 5) The horizontal and vertical sync processor IC (IC401) has a sync detector, a saw-tooth generator, and drive function, And outputs horizontal and vertical drive signal to control screen distortions

5. D/D Converter Circuit.

To obtain constant high voltage, this circuit supplies controlled DC voltage for FBT and horizontal deflection circuit according to the horizontal sync frequency.

6. X-RAY Protection Circuit

When the high Voltage reaches to 29kV in an abnormal case, the high voltage detector circuit, R818,D721,C739-1 R416, C409 start operation to shut down high voltage circuit.

7. Horizontal S-correction Circuit.

This circuit corrects the horizontal linearity for each horizontal sync frequency.

8. Horizontal drive and Output Circuit.

This circuit is a horizontal deflection amplifier for raster scan.

9. ABL Circuit

This circuit limits the beam-current for the reliability of CDT

10. Vertical Output Circuit

This circuit takes the vertical ramp wave from the TDA4867J (IC601) and perform the vertical deflection by supplying the saw-tooth wave current to the vertical deflection yoke.

11. Blanking and Brightness Control Circuit.

Blanking circuit eliminates the retrace line by supplying a negative pulse wave to the G1 of the CDT. Brightness control circuit is used for control of the screen brightness by changing the DC level G1.

12. Image Rotation (Tilt) Circuit.

This circuit corrects the tilt of the screen by supplying the image rotation signal to the tilt coil which is attached near the deflection yoke of the CDT

13. OSD (On Screen Display) Circuit.

This circuit displays information of the monitor's status on the screen.

DESCRIPTION OF BLOCK DIAGRAM

14. Video Processor Circuit.

Video processor circuit consists of the video drive output block. The video drive IC(IC302) receives the video signal from PC. The gain of each channel is controlled by MICOM through IIC. The cut-off circuit compensates different voltage of each channel between the cathode and the G1 of the CDT

15. Video Pre-Amp Circuit.

This circuit amplifies the analog video signal from 0~0.7 V to 0~4 V. It is operated by taking the clamp, R,G,B drive and contrast signal from the MICOM (IC401)

16. Video Output Amp Circuit.

This circuit amplifies the video signal which comes from the video pre-amp circuit and amplified it to applied the CDT cathode

ADJUSTMENT

1. Preparation for Service Adjustment

GENERAL INFORMATION

All adjustment are thoroughly checked and corrected when the monitor leaves the factory, but sometimes several adjustments may be required. Adjustment should be following procedure and after warming up for a minimum of 30 minutes.

- Alignment appliances and tools.
 - IBM compatible PC.
 - Programmable Signal Generator.
(eg. VG-819 made by Astrodesign Co.)
 - EPROM or EEPROM with saved each mode data.
 - Alignment Adaptor and Software.
 - Digital Voltmeter.
 - White Balance Meter.
 - Luminance Meter.
 - High-voltage Meter.

AUTOMATIC AND MANUAL DEGAUSSING

The degaussing coil is mounted around the CDT so that automatic degaussing when turn on the monitor. But a monitor is moved or faced in a different direction, become poor color purity cause of CDT magnetized, then press DEGAUSSING on the OSD menu.

ADJUSTMENT PROCEDURE & METHOD

- Install the cable for adjustment such as Figure 1 and run the alignment program on the DOS for IBM compatible PC.
- Set external Brightness and Contrast volume to max position.

1. Adjustment for B⁺ Voltage.

- 1) Display cross hatch pattern at Mode 4.
- 2) Check D961 cathode voltage within $50V \pm 1V$.

2. Adjustment for High-Voltage.

- 1) Display cross hatch pattern at Mode 4.
- 2) Enter the SVC SUB menu as the following instruction.
- 3) Adjust H/Voltage to $24.5kV \pm 0.1 kV$ by adjust 1-P value.

2. Adjustment by Service Hot key

How to enter SVC HOT KEY

1. Press Menu and OSD window will appear.
2. While OSD window is displayed, ★★ is seen on the left bottom of OSD window.
3. Press ⌄ + power switch simultaneously and the screen will immediately refresh.
4. Press Menu and make sure that ★★ is changed to 1 2.
5. Follow the menu on the left of OSD window to find 12 and OSD will change as shown in the figure.
6. Select Degauss in the above figure and then press Select and ▶ to enter the screen of the SUB menu.
(Back Raster for Pattern)

FOS SPEC

1. Size

H : $270 \pm 4mm$

V : $200 \pm 4mm$

Scanning frequency : All Mode (Mode 1~4)

Display image : Cross hatch pattern

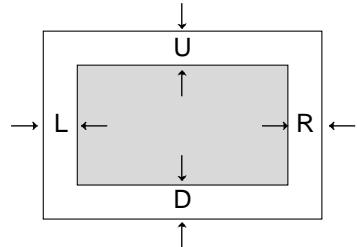
2. Centering

Scanning frequency : All Mode (Mode 1~4)

Display image : Crosshatch pattern

Horizontal : 10 Row

Vertical : 8 Row



H : $|L-R| \leq 4mm$, V : $|U-D| \leq 4mm$

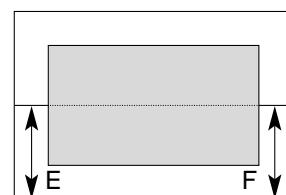
3. Tilt

Scanning frequency : All Mode (Mode 1~4)

Display image : Crosshatch pattern

Horizontal : 10 Row

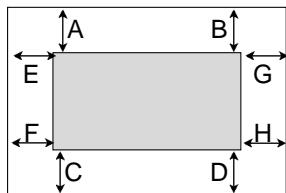
Vertical : 8 Row



Tilt : $|E-F| \leq 2.0mm$

4. Distortion

Scanning frequency : All Mode (Mode 1~4)
 Display image : Crosshatch pattern
 Horizontal : 10 Row
 Vertical : 8 Row



$$|A-B| \leq 2.0\text{mm}, |C-D| \leq 2.0\text{mm} \\ |E-F| \leq 2.0\text{mm}, |G-H| \leq 2.0\text{mm}$$

5. Disp Size drift

- $\pm 4\text{mm}$: 25°C Standard, 10°C , 35°C
- $\pm 0.5\text{mm}$: $180\text{V} \sim 264\text{V}$

6. Linearity

				Y1
				Y2
				Y3
				Y4
X1	X2	X3	X4	

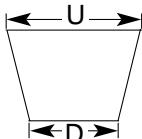
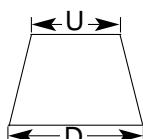
Formula : $\{(Max - Min) / Max\} \times 100(\%)$
 Criteria : H - 10% Max. (Upper 40kHz)
 14% Max. (Less 40kHz)
 V - 8% Max.

7. Regulation

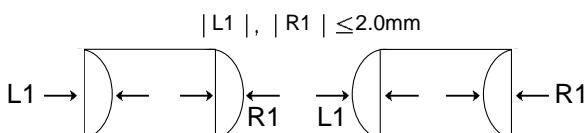
Luminance $\leq 2\text{mm}$
 Dynamic(lode) $\leq 2\text{mm}$
 Scanning frequency : All Mode (Mode 1~4)

8. Trapezoid

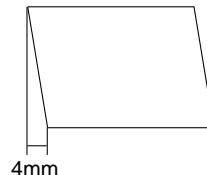
$$|U-D| < 4\text{mm}$$



9. Pin Balance



10. Parallelogram



11. Adjustment of white balance (Adjustment of chromaticity diagram)
 *(Adjustment of white balance must be made after entering Hot Key Mode and DEGAUSS.)

CONDITIONS

Signal: 54 kHz / 85 Hz
 Display image: Back raster (Color 0,0)
 Contrast: Maximum
 Brightness: Maximum
 Color temperature: 9300K

11-1. Adjustment of cut off (Adjustment of back raster)

11-1(a). Before adjustment, press Menu and Degauss to remove.

=> Enter hot key mode.

Adjust Brightness and Contrast to Max in OSD window.

(1) Adjust cut off (back raster) first. Enter DEGAUSS in the Menu and modify the following data.

Modify RCUT to Min ,
 Modify GCUT To Min ,
 Adjust to BCUT Data = 127 (7F (h)) ,
 Adjust to SBRT Data = 205 (CD (h)).

(2) Turn FBT screen volume on "CRT COLOR ANALYZER CA-100" equipment to adjust Brightness to $0.4 \pm 0.05\text{FL}$.

(3) Adjust RCUT, GCUT, and SBRT to set chromaticity diagram at :

x: 0.283 ± 0.005
 y: 0.298 ± 0.005
 Y: $0.40 \pm 0.05\text{FL}$

* If color values would not be matched desirable values, repeat sequence 1 and 2 after readjusting "GREEN CUTOFF" control a little different.

11-2. Adjustment of White Balance

After finishing adjustment of cut off (back raster), approve "Color(15.0) Full white pattern".

Adjust BDRV Data = 80, SCON=127.

Adjust RDRV and GDRV to set chromaticity diagram at :

x: 0.283 ± 0.005

y: 0.298 ± 0.005

Approve "Window pattern (70x70mm)" to adjust

S-CON to Y : 50 ± 1 FL.

Approve "Color (15.0) Full white pattern" again and adjust ABL Data to Y : 32 ± 1 FL

12. Focus Adjustment

CONDITIONS

Scanning frequency : All Mode (Mode 1~4)

Display image: Character pattern

Brightness: Cut off point

Contrast: Maximum

PROCEDURE

1. Adjust the Focus VR on the FBT to display the sharpest image possible.

2. Use Locktite to seal the Focus VR in position.

13. Color Purity Adjustment

Color purity is the absence of undesired color.

Conspicuous mislanding (unexpected color in a uniform field) within the display area shall not be visible at a distance of 50 cm from the CRT surface.

CONDITIONS

Orientation: Monitor facing east

Scanning Frequency: 1024 x 768@85Hz(69kHz/85Hz)

Display image: White flat field

Luminance: Cut off point at the center of the display area

Note: Color purity adjustments should only be attempted by qualified personnel.

PROCEDURE

For trained and experienced service technicians only.

Use the following procedure to correct minor color purity problems:

1. Make sure the display is not affected by external magnetic fields.
2. Very carefully break the glue seal between the 2-pole purity convergence magnets (PCM), the band and the spacer.
3. Make sure the spacing between the PCM assembly and the CRT stem is $29 \text{ mm} \pm 1 \text{ mm}$.
4. Display a green pattern over the entire display area.
5. Adjust the purity magnet rings on the PCM assembly to display a pure green pattern.
(Optimum setting: $x = 0.295 \pm 0.015$,
 $y = 0.594 \pm 0.015$)
6. Repeat steps 4 and 5 using a red pattern and then again, using a blue pattern.

Table 4-6. Color Purity Tolerances

Red:	$x=0.620 \pm 0.015$	$y=0.334 \pm 0.015$
Green:	$x=0.620 \pm 0.015$	$y=0.334 \pm 0.015$
Blue:	$x=0.620 \pm 0.015$	$y=0.334 \pm 0.015$

(For 9300K color adjustment: $x = 0.283 \pm 0.02$,
 $y = 0.298 \pm 0.02$)

7. When you have the PCMs properly adjusted, carefully glue them together to prevent their movement during shipping.

3. Adjustment Using Service software Program (Adjustment Program)

1. Adjustment for Factory Mode (Preset Mode).

- 1) Display cross hatch pattern at Mode All.
- 2) Run alignment program for 505EM on the IBM compatible PC.
- 3) EEPROM → ALL CLEAR → Y(Yes) command.
<Caution> Do not run this procedure unless the EEPROM is changed. All data in EEPROM (mode data and color data) will be erased.
- 4) COMMAND → PRESET START → Y(Yes) command.
- 5) DIST. ADJ. → FOS. ADJ command.
- 6) Adjust H-POSITION as arrow keys to center of the screen.
- 7) Adjust H-SIZE as arrow keys to 270 ± 2 mm.
- 8) Adjust V-POSITION as arrow keys to center of the screen.
- 9) Adjust V-SIZE as arrow keys to 200 ± 2 mm.
- 10) Adjust TRAPEZOID as arrow keys to be the best condition.
- 11) Adjust SIDE PINCUSHION as arrow keys to be the best condition.
- 12) Adjust TILT to be the best condition(Optional).
- 13) Display cross hatch pattern at Mode 4.
- 14) DIST. ADJ. → BALANCE DATA command.
- 15) Adjust balance of Pin-Balance as arrow keys to be the best condition.
- 16) Adjust parallelogram as arrow keys to be the best condition.
- 17) Save of the Mode.
- 18) Save of the System.
- 19) Display from Mode 4 and repeat above from number 6) to 16).
- 20) COMMAND → PRESET EXIT → Y (Yes) command.

2. Adjustment for White Balance and Luminance.

- 1) Set the White Balance Meter.
- 2) Press the DEGAUSSING on the OSD menu for demagnetization of the CDT.
- 3) Display color 0,0 pattern at Mode 4.
- 4) COMMAND → PRESET START → Y(Yes) command.
- 5) Set Brightness and Contrast to max position.
- 6) COLOR ADJ. → LUMINANCE command of the alignment program.
- 7) COLOR ADJ. → BIAS ADJ. command of the alignment program.
- 8) Check whether blue color or not at R-BIAS and G-BIAS to min position, Sub-Brightness to 205 (CD(h))position, B-Bias to 127(7F(h))position. If it's not blue color, the monitor must repair.
- 9) Adjust Screen control on the FBT to 0.4 ± 0.05 FL of the raster luminance.
- 10) Adjust R-BIAS and G-BIAS command to $x=0.283 \pm 0.006$ and $y=0.298 \pm 0.006$ on the White Balance Meter with PC arrow keys.
- 11) Display color 15,0 Full White(70x70mm) at mode 4.
- 12) DRIVE ADJ command.
- 13) Set B-DRIVE to 80(50(h)) at DRIVE of the alignment program.
- 14) Adjust R-DRIVE and G-DRIVE command to white balance $x=0.283 \pm 0.003$ and $y=0.298 \pm 0.003$ on the White Balance Meter with PC arrow keys.
- 15) Adjust SUB-CONTRAST command to 50 ± 1 FL of the raster luminance.
- 16) Display color 15,0 full white patten at Mode 4.
- 17) COLOR ADJ. → LUMINANCE → ABL command.
- 18) Adjust ABL to 32 ± 1 FL of the luminance.
- 19) Exit from the program.

4. EDID Data Edit Using Service software Program

4.1 Read and Modify EDID Data

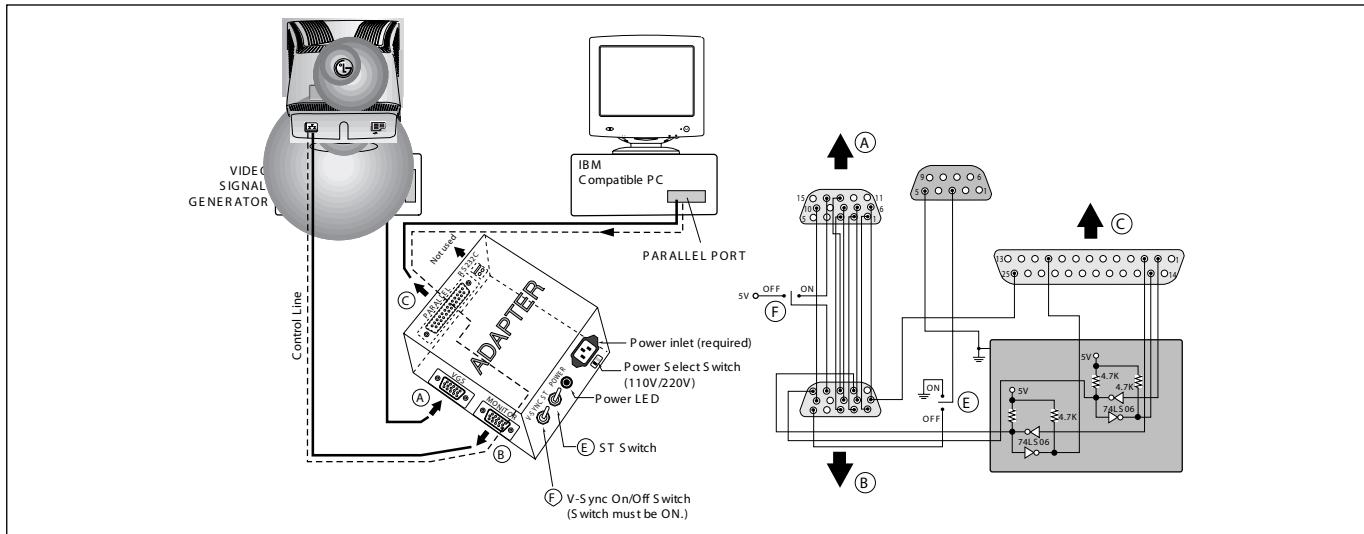
- 1) Connector the monitor and adjust device as Figure1
- 2) Display color 15,0 cross hatch pattern at Mode 4.
- 3) Use EDIT – MODEL SEL. command to select the right model info file.
- 4) Use EDIT – EDID INFO command and return to read the EDID Data.
- 5) Modify the EDID Data if needed and using F10 to save the change and exit.

4.2 Write EDID Data.

- 1) Display color 15,0 cross hatch pattern at Mode 4.
- 2) Use EEPROM – Write EDID command and confirm “EDID Write OK!!” message of monitor.
- 3) Exit from the alignment program.
- 4) Power switch OFF/ON for EDID data save.

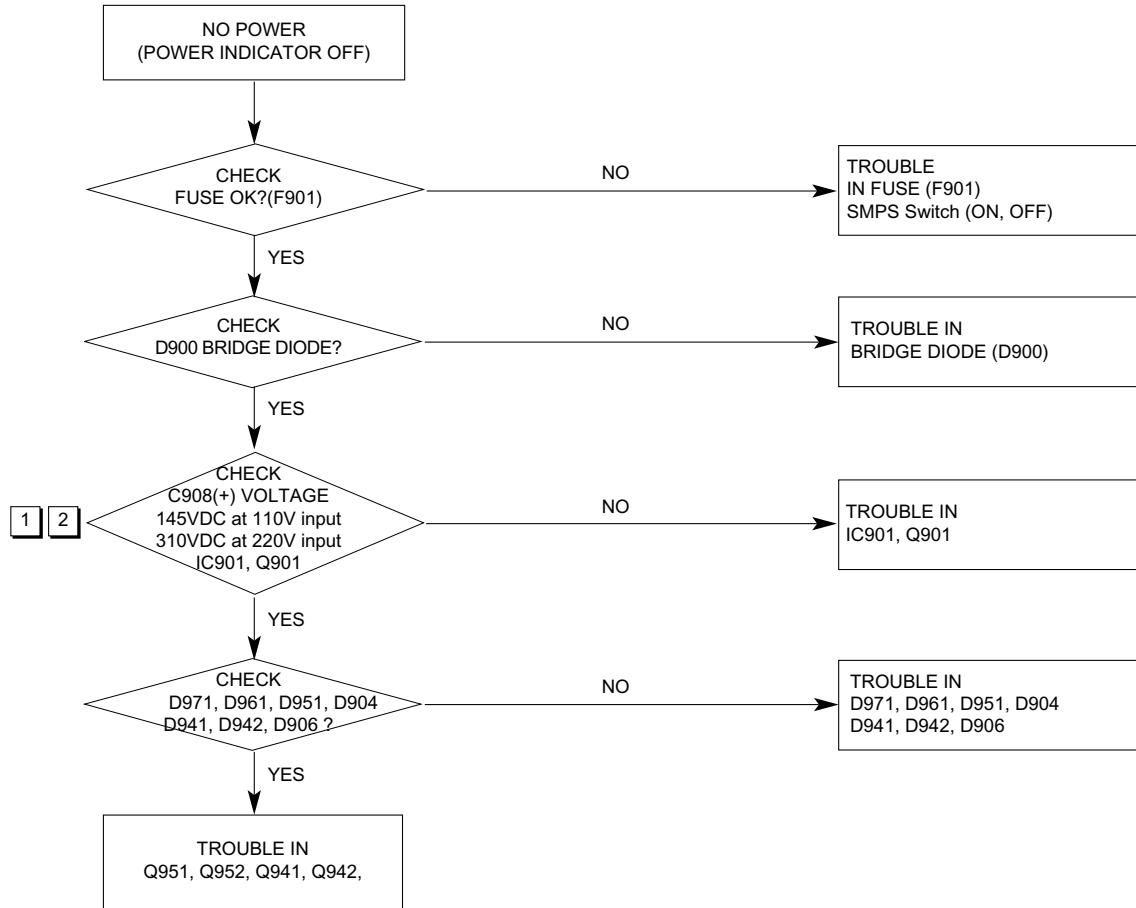
	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	
00		00	FF	FF	FF	FF	FF	00	1E	6D	83	3B	*01	00	00	00	
10		**01	0F	01	03	78	1C	15	B0	EA	60	59	A4	54	46	9B	24
20		10	48	4C	BF	E8	00	31	59	45	59	01	01	01	01	01	01
30		01	01	01	01	01	01	64	19	00	40	41	00	26	30	18	88
40		36	00	OE	C8	10	00	00	18	F9	15	20	F8	30	58	1F	20
50		20	40	13	00	OE	C8	10	00	00	1E	00	00	00	FD	00	32
60		78	1E	36	07	00	0A	20	20	20	20	20	20	20	00	00	FC
70		00	35	30	35	45	0A	20	20	20	20	20	20	20	20	00	***

Figure 1. Cable Connection

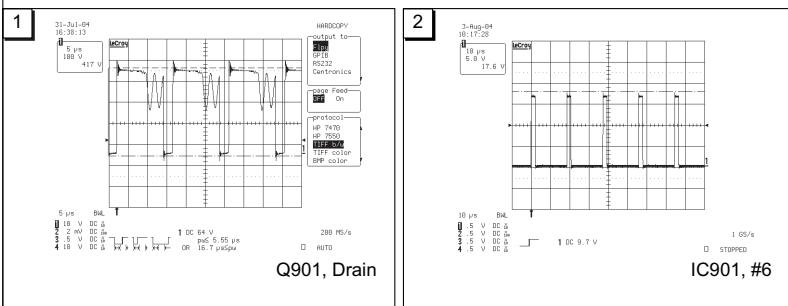


TROUBLESHOOTING GUIDE

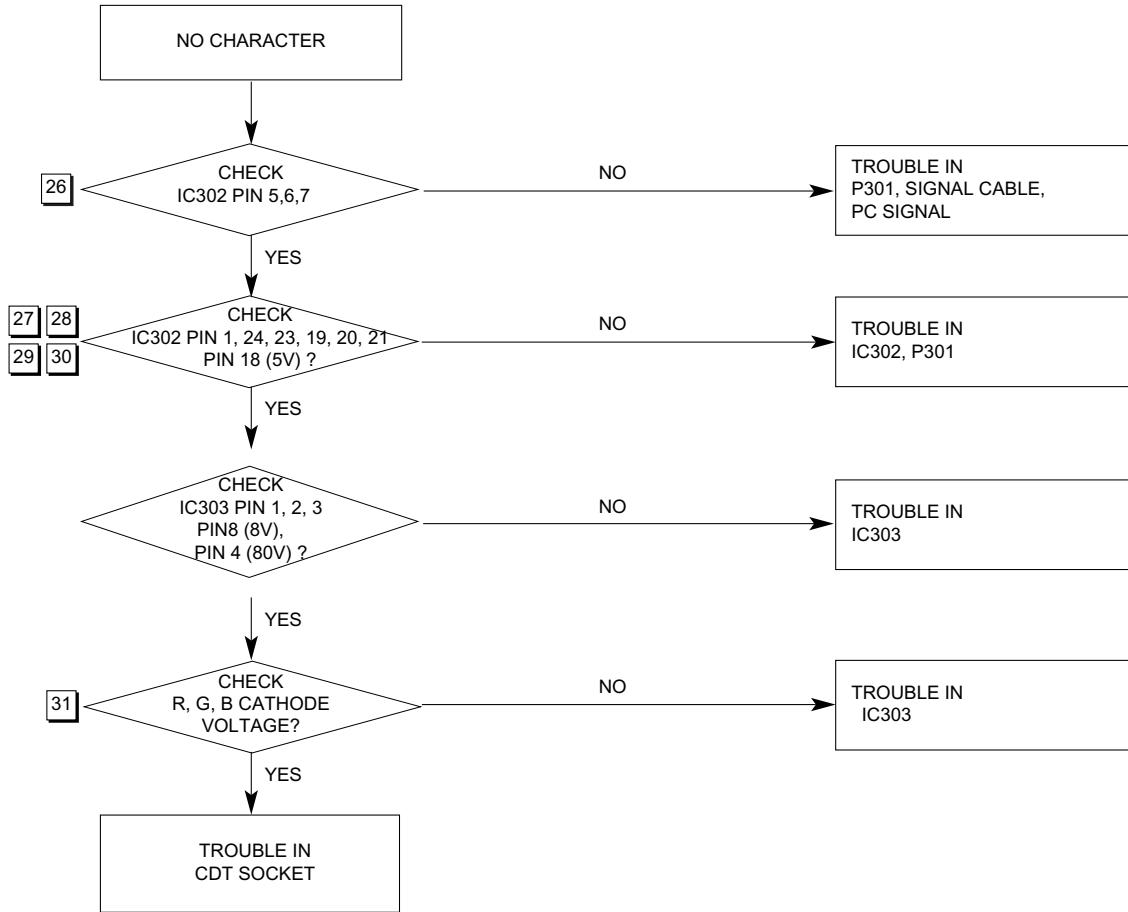
1. NO POWER



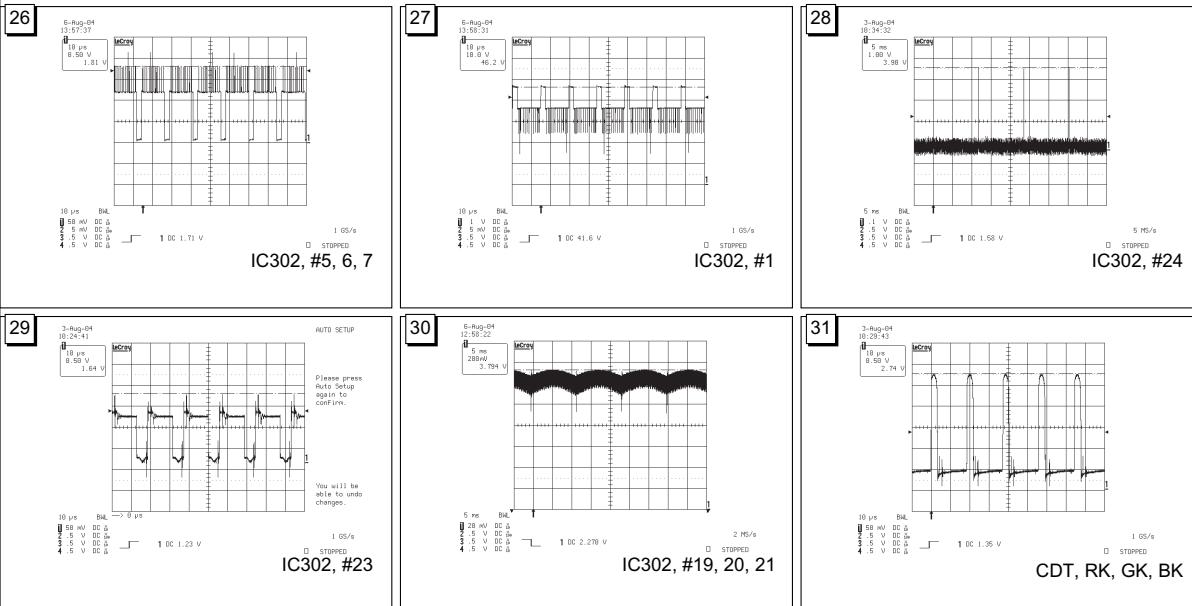
Waveforms



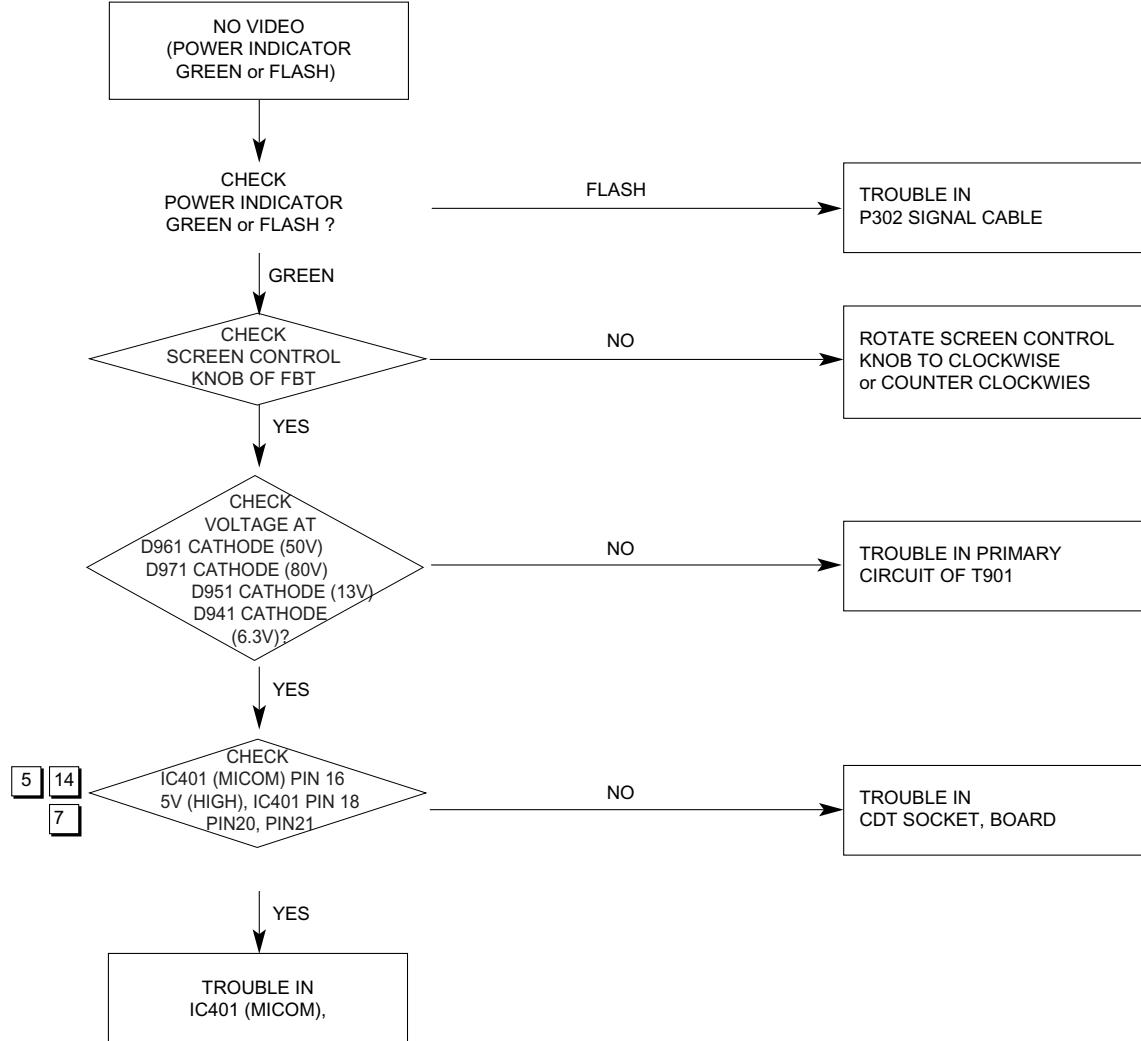
2. NO CHARACTER



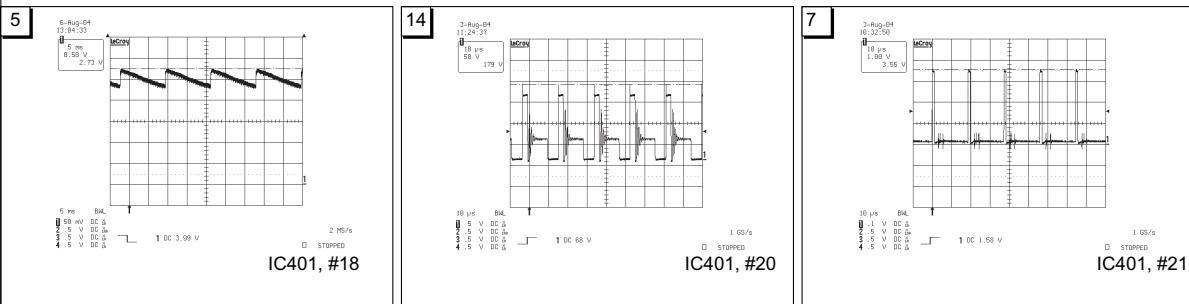
Waveforms



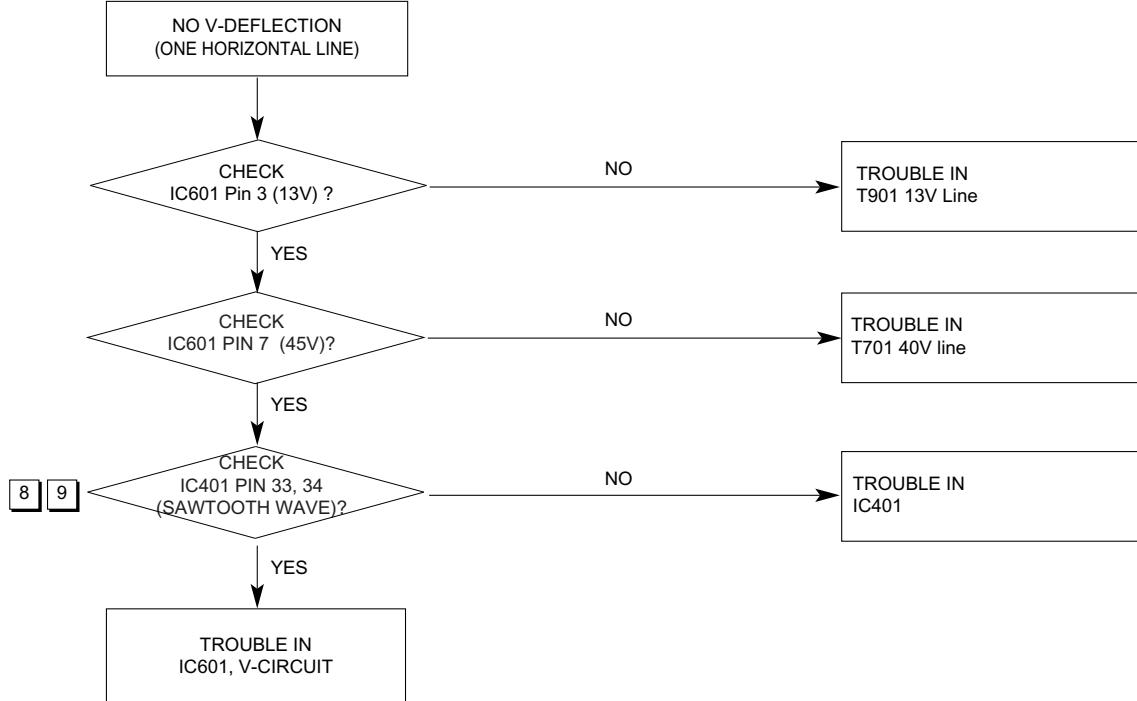
3. NO RASTER



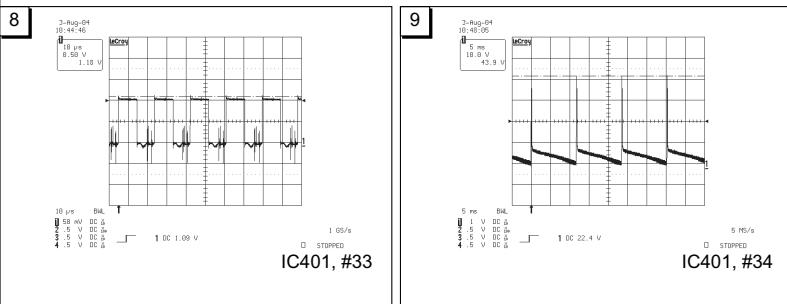
Waveforms



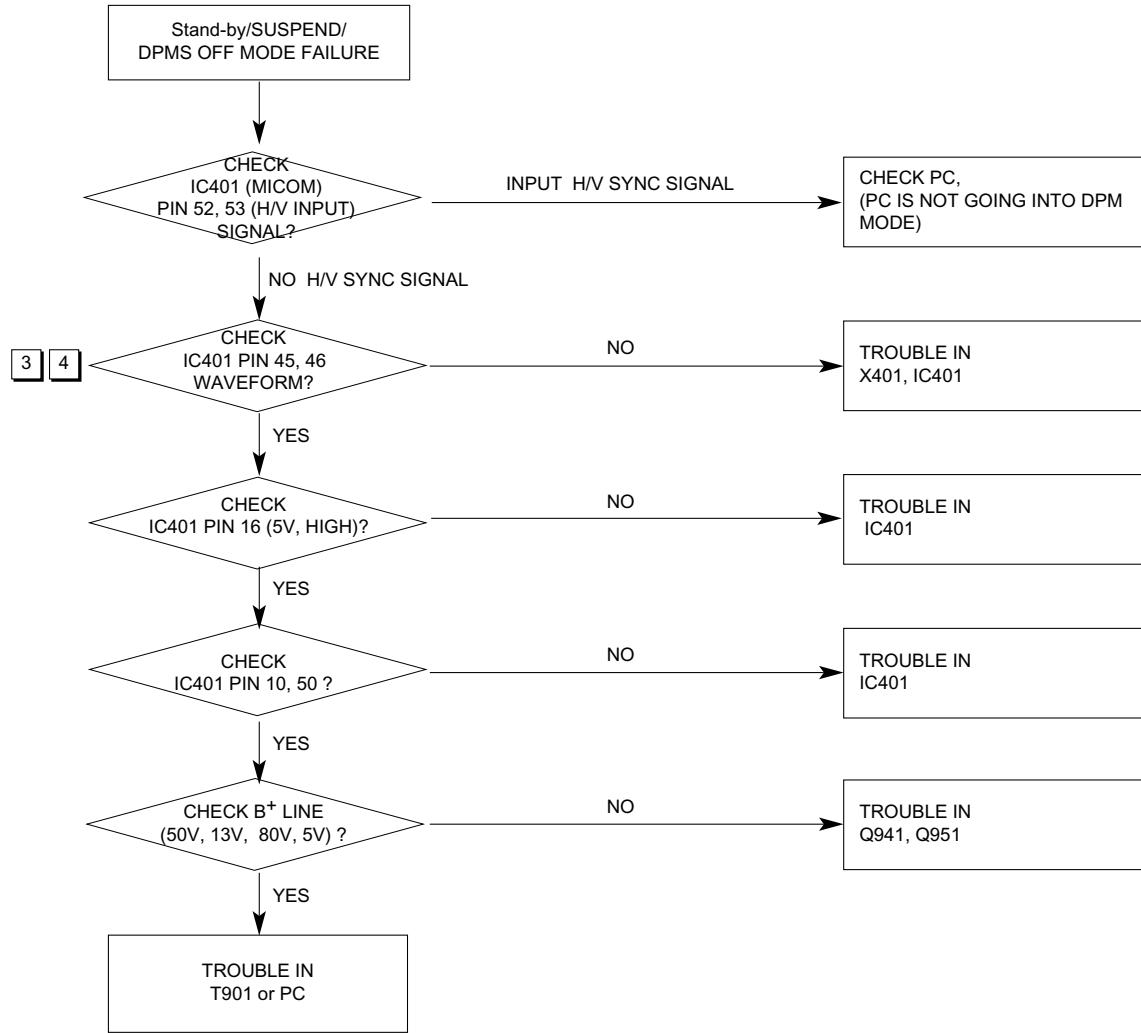
4. NO VERTICAL DEFLECTION



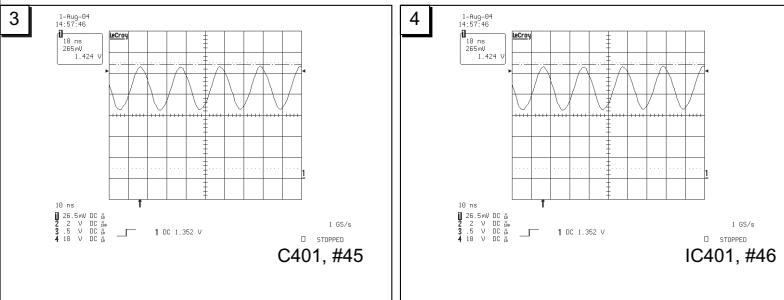
Waveforms



5. TROUBLE IN DPM



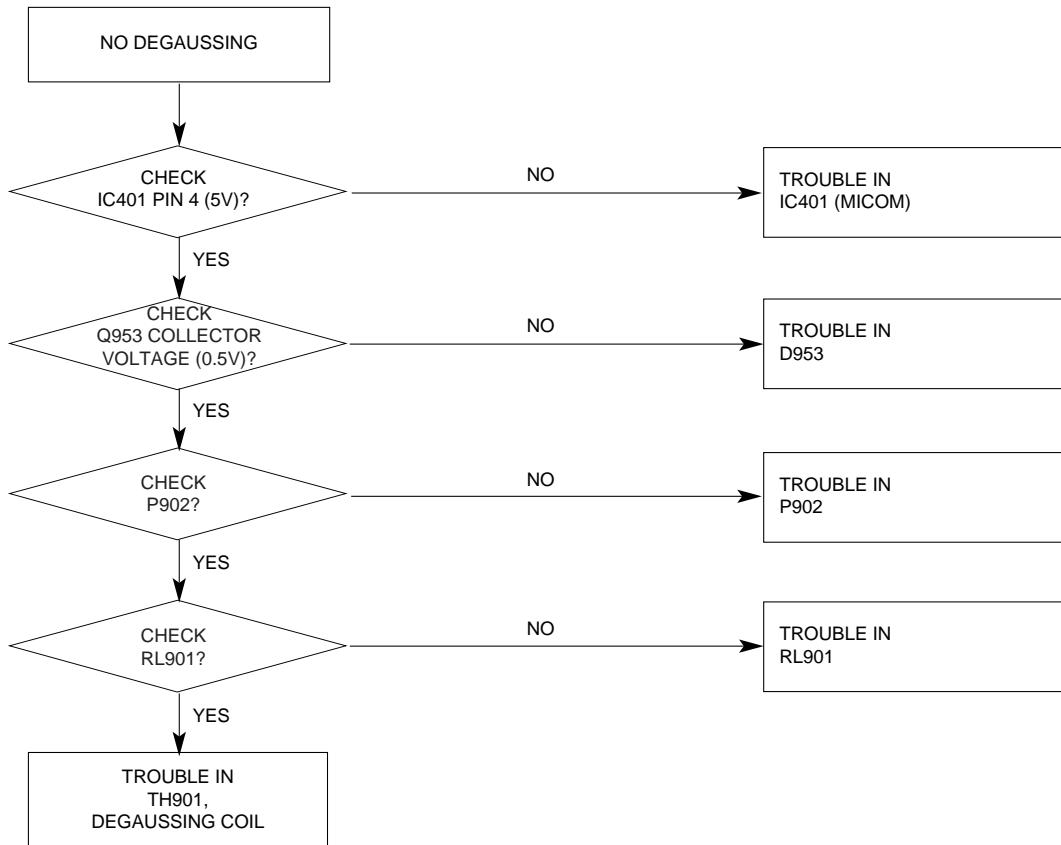
Waveforms



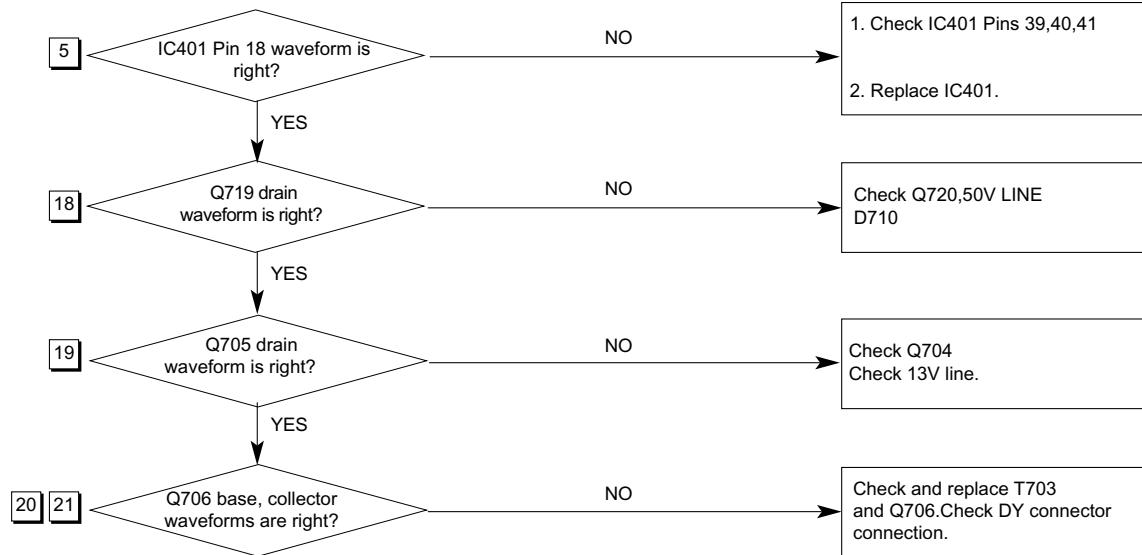
DPMS TABLE

ITEM MODE	H/V SYNC	VIDEO	LED
NORMAR	ON/ON	NORMAL	GREEN
STAND-BY	OFF/ON	OFF(0V)	FLASH
SUSPEND	ON/OFF	OFF(0V)	FLASH
OFF	OFF/OFF	OFF(0V)	FLASH

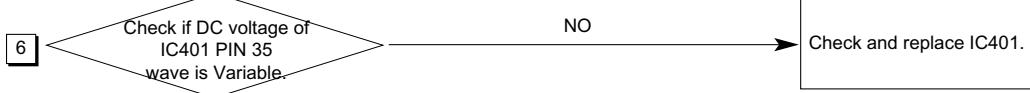
6. NO DEGAUSSING



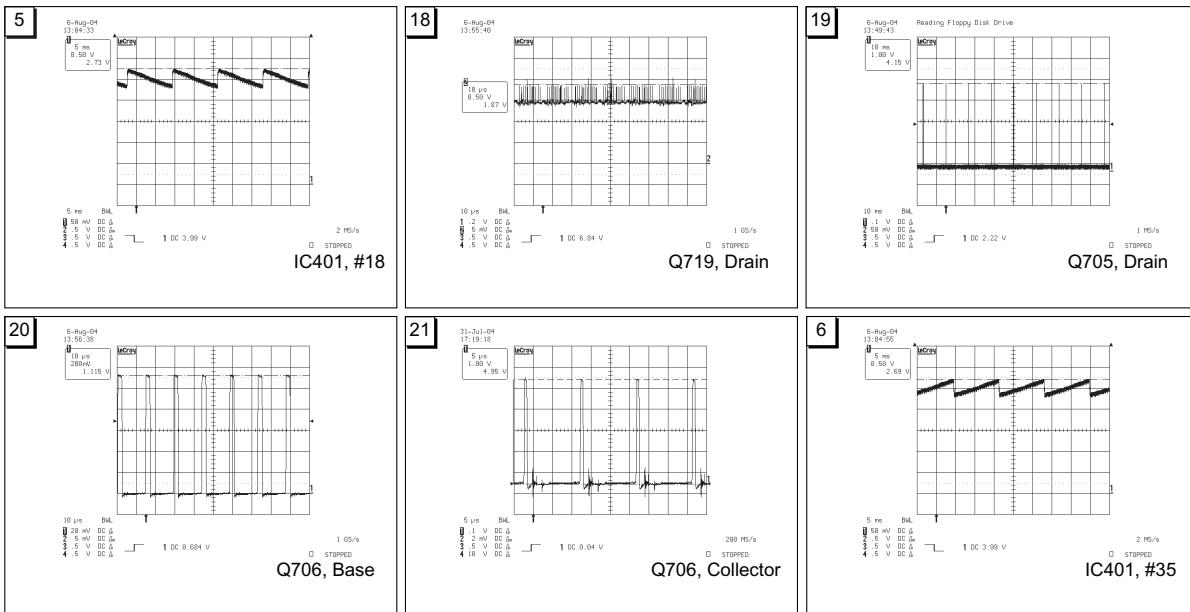
7. H_Deflection Failure



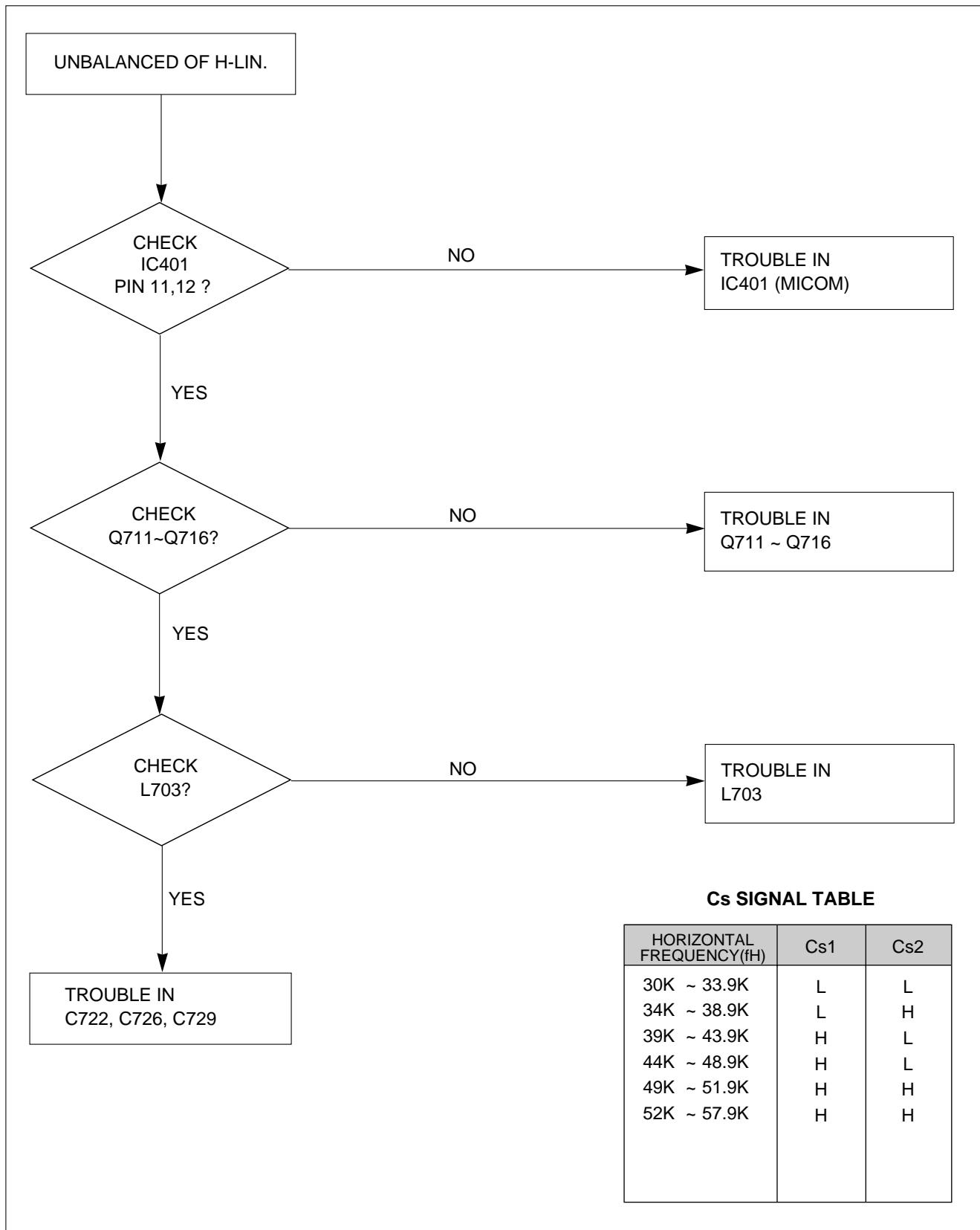
8. Invariable H_Size



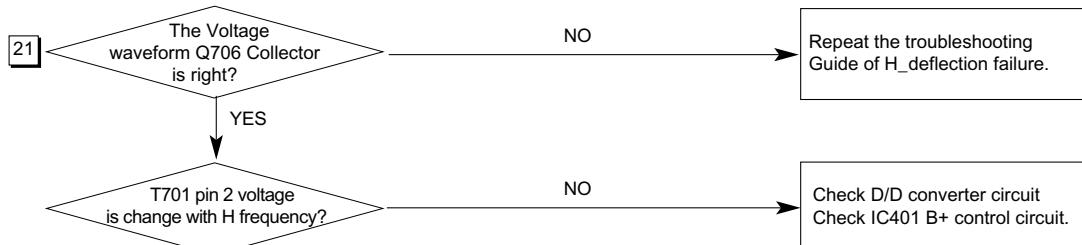
Waveforms



8. TROUBLE IN H-LINEARITY



9. Abnormal H_Size



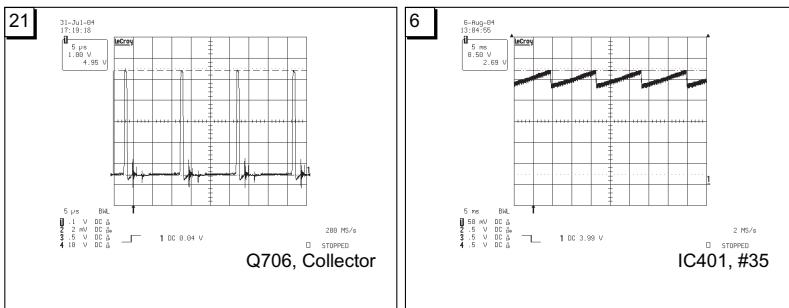
10. Side Pin or T rap Failure



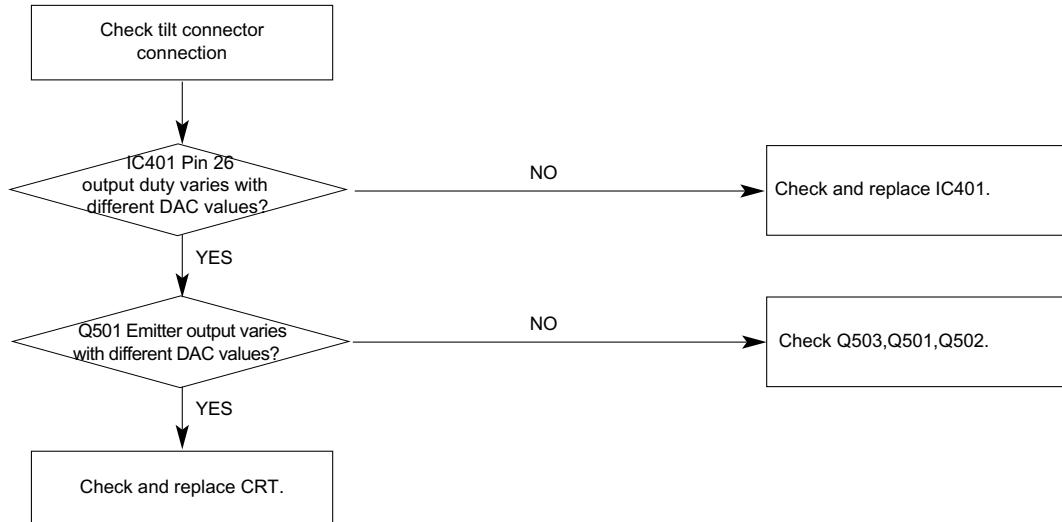
11. Para. or Pin Balance Failure

Replace IC401.

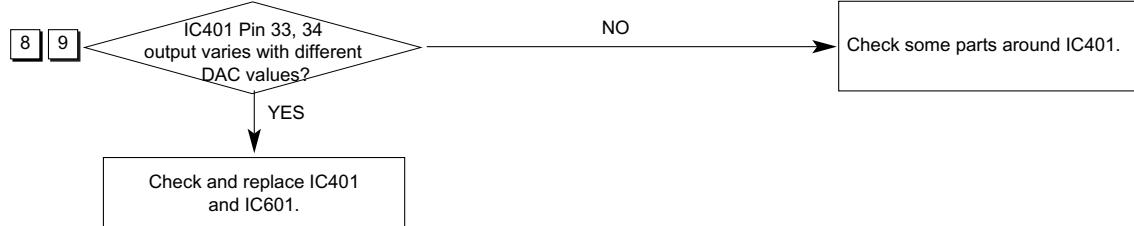
Waveforms



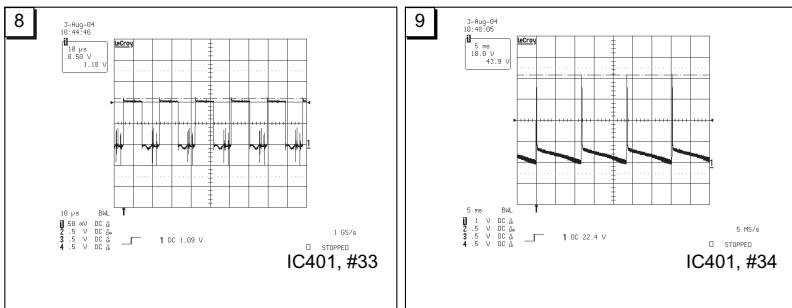
12. Tilt Failure (optional)



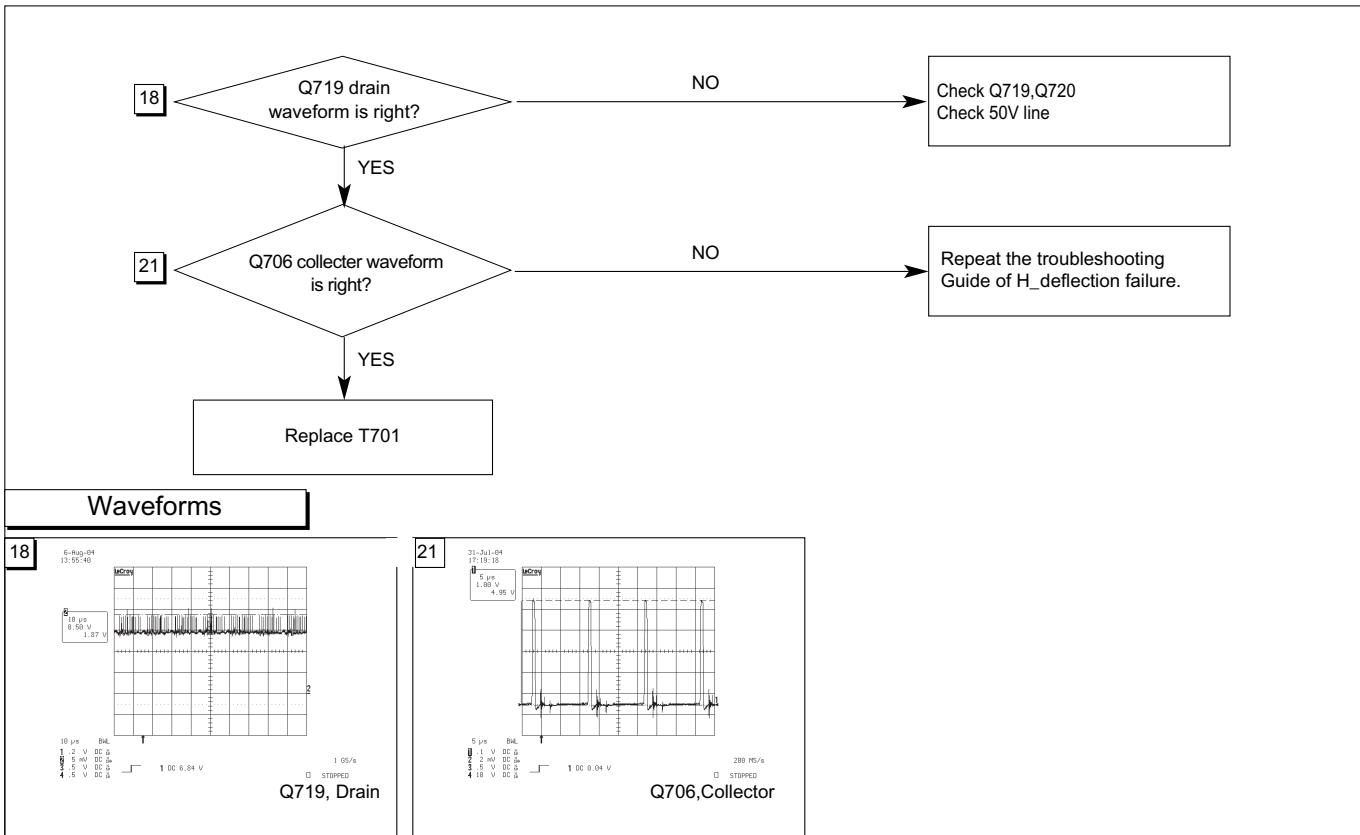
13. V Size or Pos. V ariation Failure



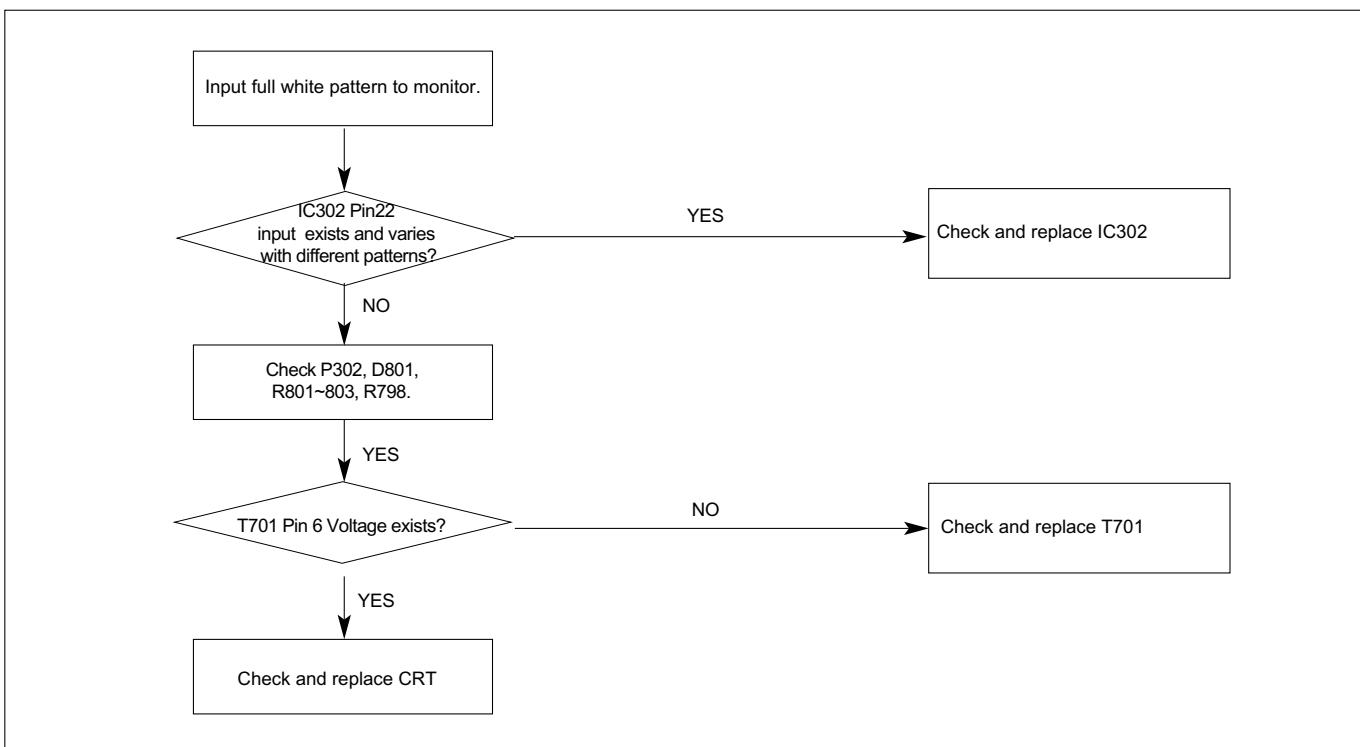
Waveforms



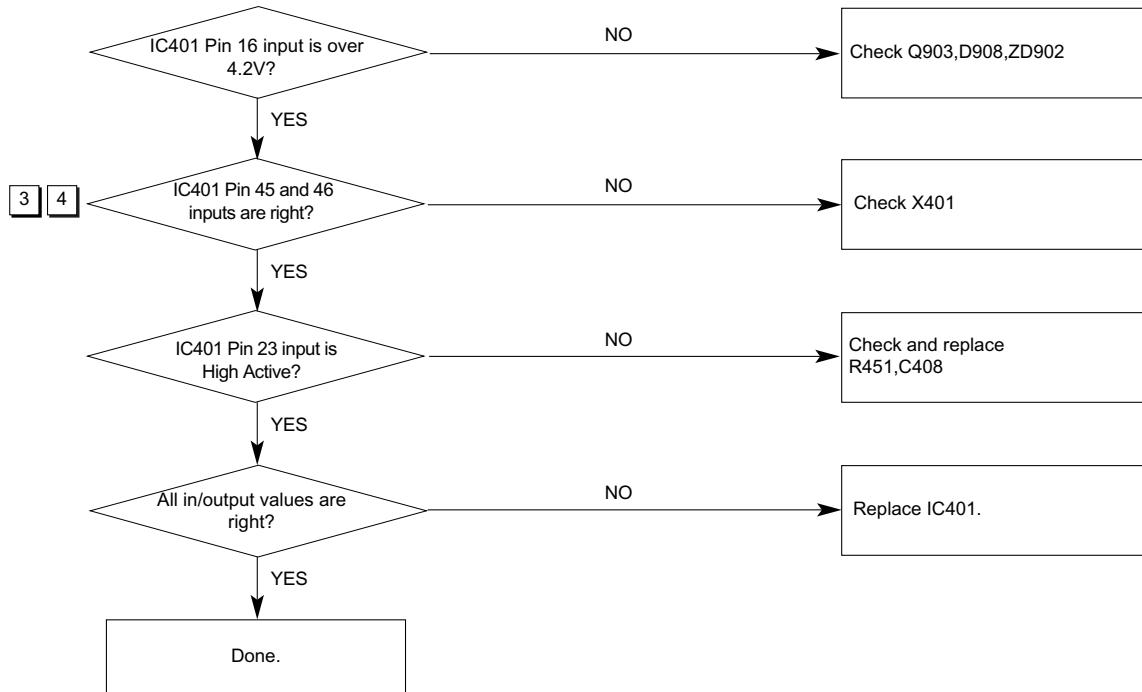
14. High Voltage Failure



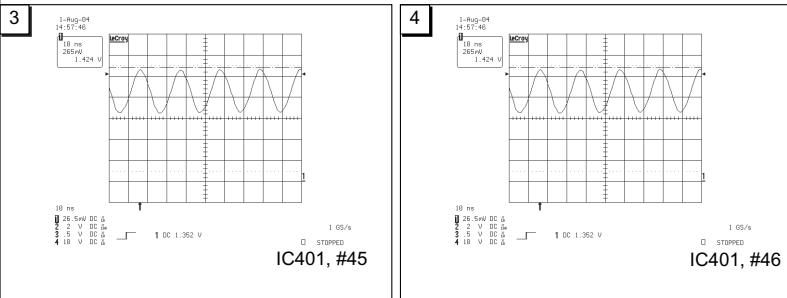
15. ABL Failure



16. Micom Failure



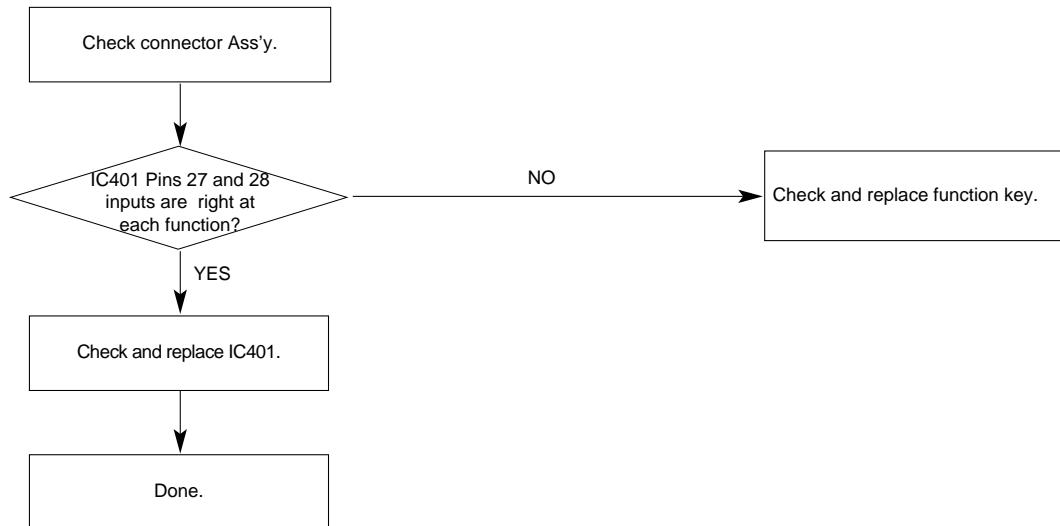
Waveforms



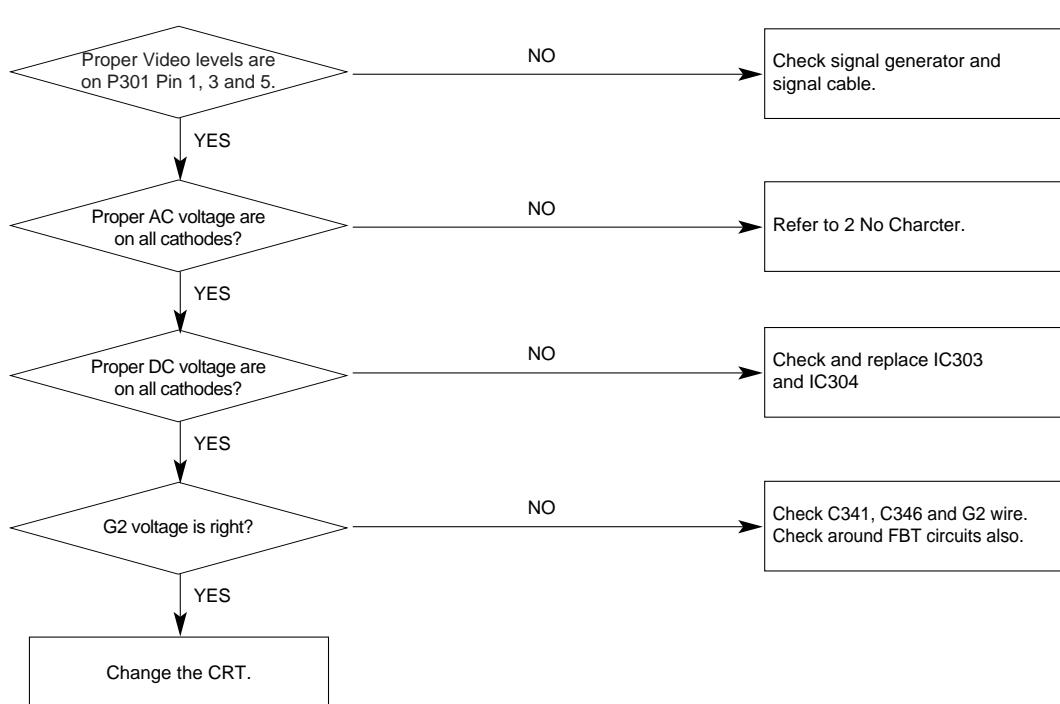
17. OSD Failure

Change IC302

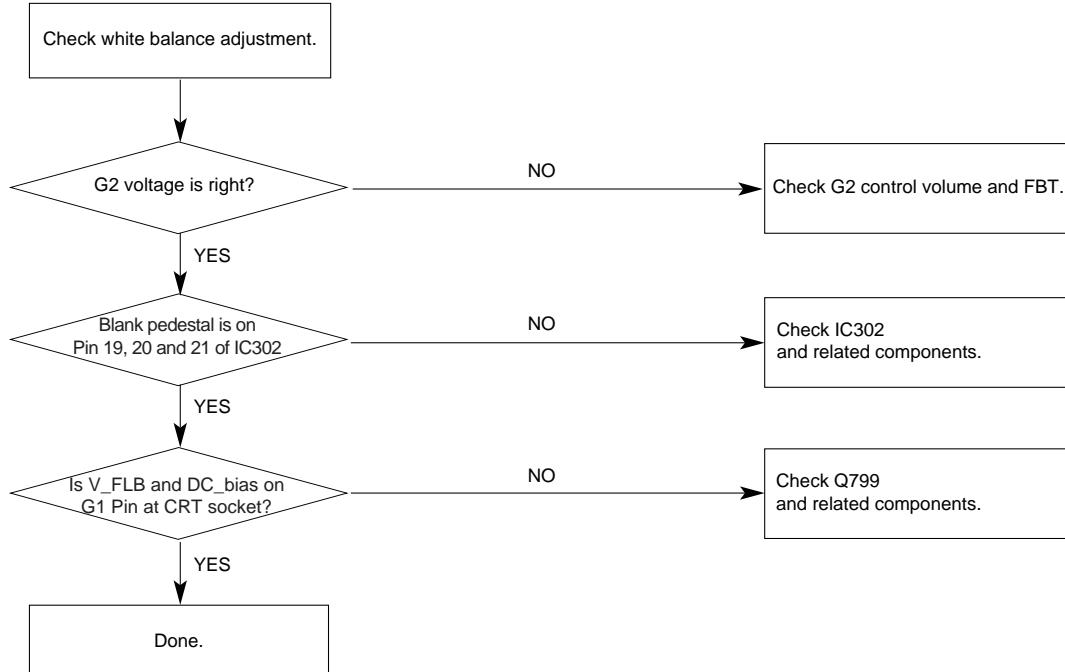
18. User Control Failure



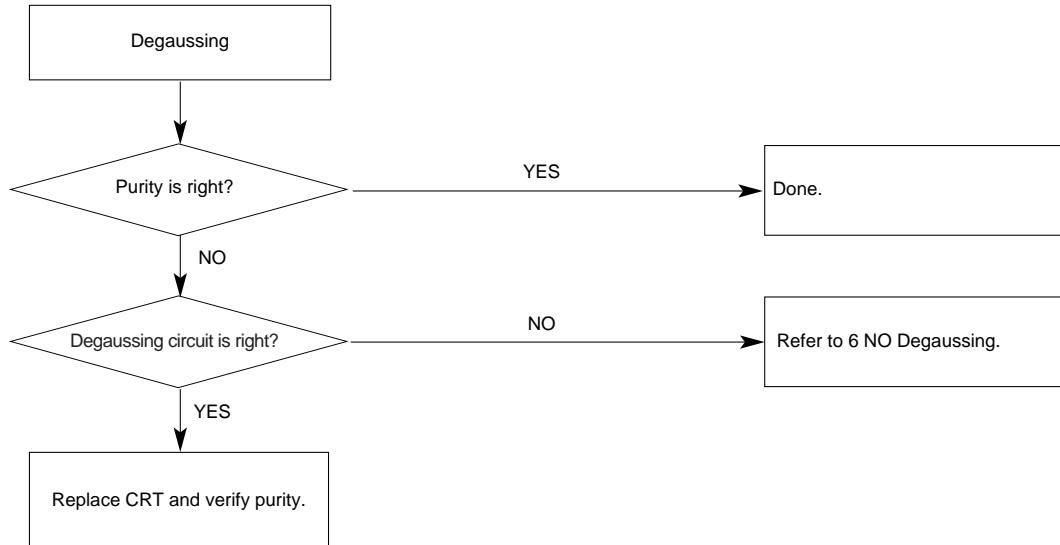
19. Missing Color



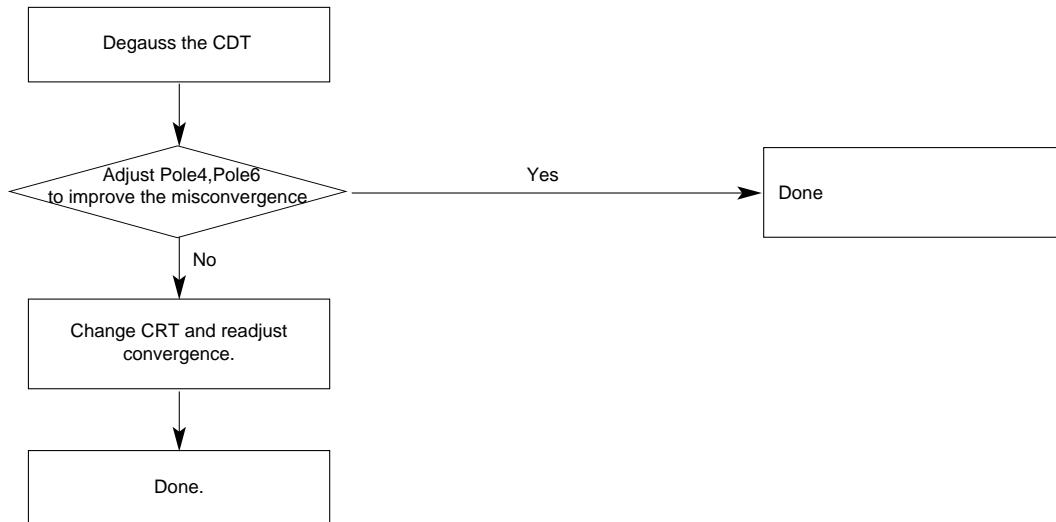
20. Visible Retrace



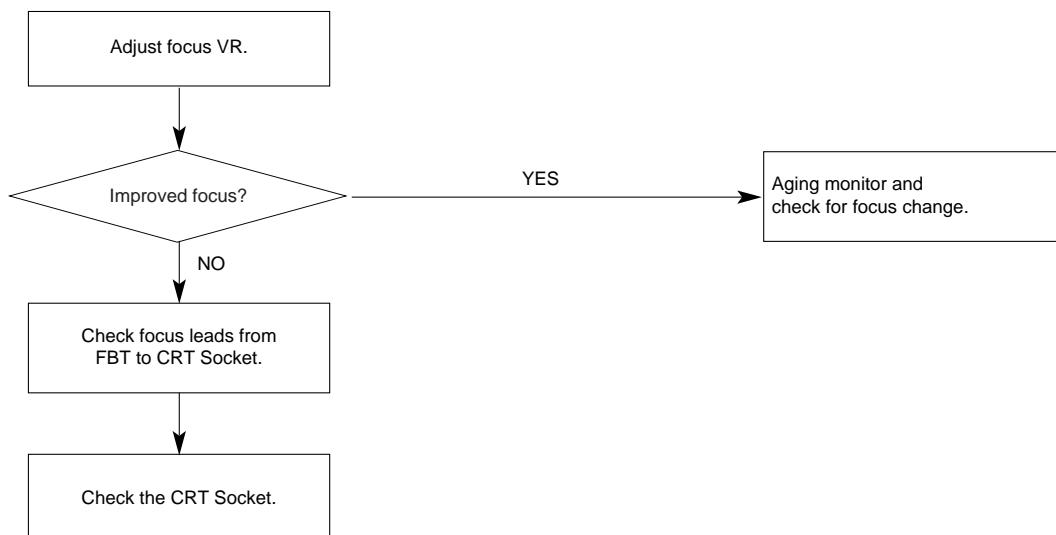
21. Purity Failure



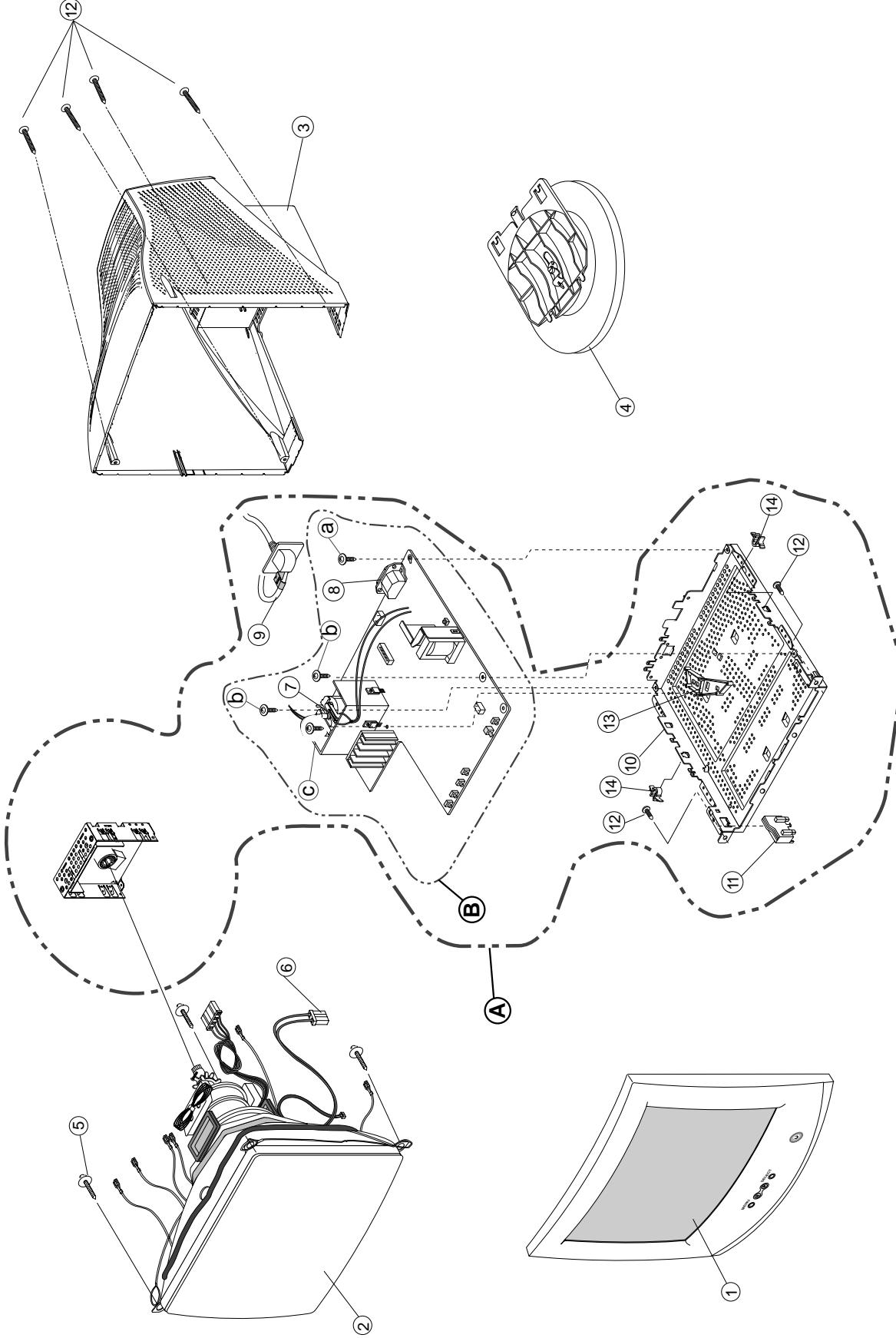
22. Misconvergence



23. Poor Focus



EXPLODED VIEW



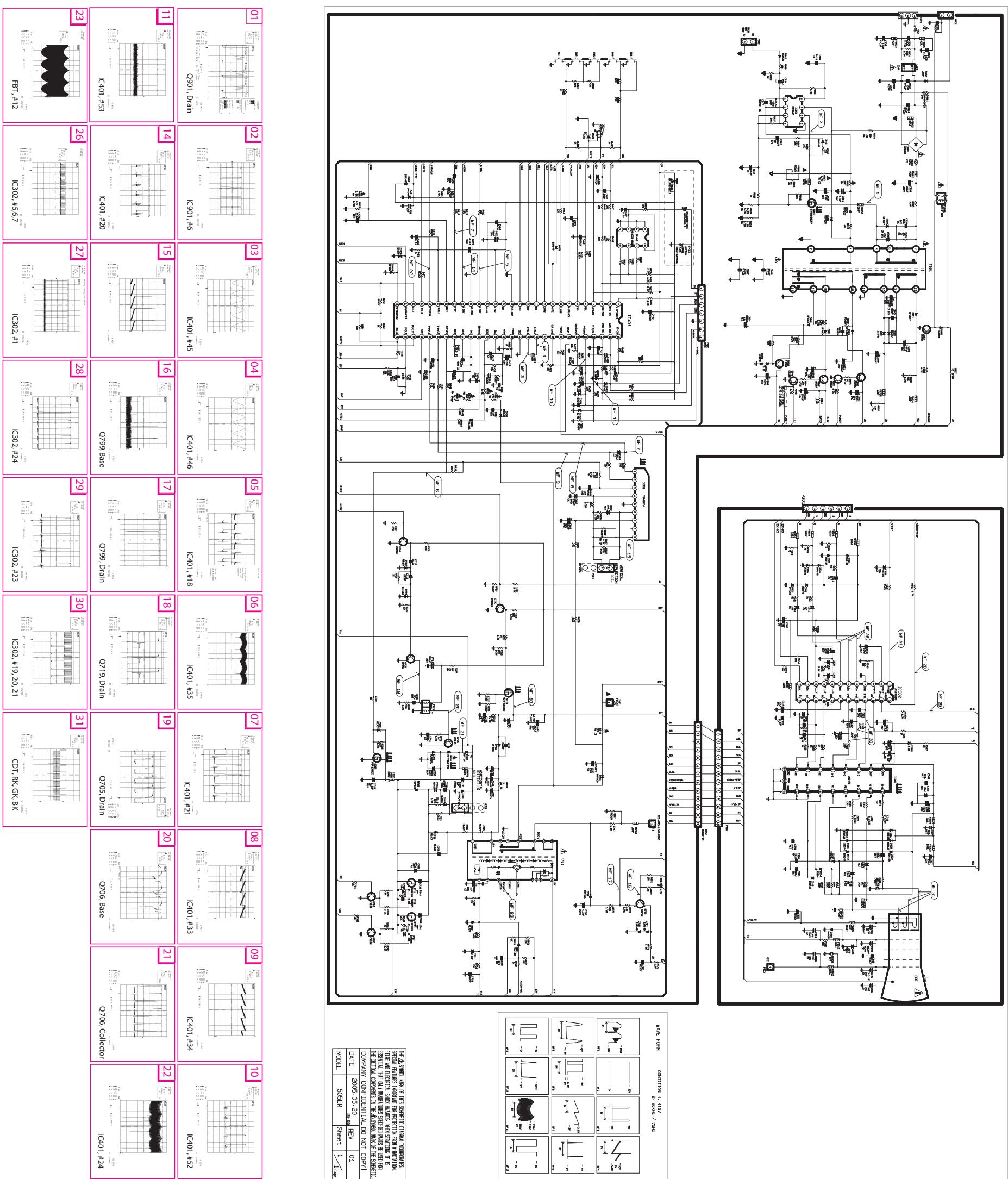
EXPLODED VIEW PARTS LIST

Ref. No.	Part No.	Description
1	3091TKB031Q	CABINET ASSEMBLY, 500EJ BRAND 3090TKB027A (RU)
	3091TKB048Q	CABINET ASSEMBLY, 500EJ BRAND B031 320T 85964 LG (EU)
2	6318L15015A	CDT(CIRC) M41LFQ803X00NGAA LG-PHILIPS 70KHZ 29.1MM FST MPR BARE(RU)
	6318L15014B	CDT(CIRC) M36LBL503X00NDDP LG-PHILIPS DI(EU)
3	3809TKB028A	BACK COVER ASSEMBLY, 505EJ 3808TKB032A (LGENT)
4	3043TKK063X	TILT SWIVEL ASSEMBLY, CB553H B056/T046 60HR,85964,NT
5	339-002D	SCREW ASSY, PHP+5*30BP(FZMY)+GW18
6	6140TC3006B	COIL,DEGAUSSING, 75D-437 KWANGSUNG CB563G NT 15"
7	6174T11006D	FBT (FLY BACK TRANSFORMER), C93 BSC24-1445 FUJIAN FURI
8	6620TKB002B	SOCKET(CIRC),POWER, SA-4S HUA JIE AC UNIVERSAL 3PIN BLACK
	6620TKB002D	SOCKET(CIRC),POWER, CDJ-3C DUOLING AC UNIVERSAL 3PIN BLACK
9	6850TA9018A	CABLE,D-SUB, UL20276-9C(4.9MM) AT 1560MM
10	4950TKS155S	METAL,SHIELD BOTTOM,CB553,0.8T,REAR(EU)
	4950TKS207A	METAL, SHIELD BOTTOM,CB553H(RU)
11	4810TKK154A	BRACKET, CB773D SUPPORTER CDT(L)
12	332-102F	SCREW, PTP+4*20BP(MSWR/FZMY)
13	4810TKK204A	BRACKET, CB77H HOLDER FBT(RU)
	4810TKK204H	BRACKET, 700BK HOLDER FBT(EU)
14	4930TKK031C	HOLDER, PCB FIX , PC+ABS
A	3313T15111A	MAIN TOTAL ASSEMBLY, 505EM BRAND CA-136(RU)
	3313915001A	MAIN TOTAL ASSEMBLY, 505EM BRAND CA-138(EU)
B	6871TMTA81A	PWB(PCB) ASSEMBLY,MAIN,505EM KLRDMT BRAND CA-138 TOTAL(RU)
	68719MT009A	PWB(PCB) ASSEMBLY,MAIN,505EM KLRDMT BRAND CA-138 TOTAL(EU)
a	332-112F	SCREW,DRAWING, D3.5 L10.0 MSWR/FZMY +SW3.5+RW3.5
b	4001TKK004E	SCREW ASSEMBLY, TAPTITE P TYPE D3.0 L10.0 MSWR/FZMY SW3+RW10
c	332-095A	SCREW, PZP+3*8 (MSWR/FZMY)

MODEL :505EM				DATE:2005.06.11
*S	*AL	LOC NO.	PART NO.	DESCRIPTION/SPECIFICATON
		C914	0CZTFT001P	ECQB1H153JM3 153J 50V TP5.0 MATSUSHITA
		C915	0CK6810K515	680PF D 50V 10% B(Y5P) TR
		C917	0CK1020K515	1000PF D 50V 10% B(Y5P) TR
		C918	0CK1040K945	"0.1UF D 50V 80%, -20% F(Y5V) TR"
		C941	0CE108CD618	"1000UF SHL,SD 10V 20% FL TP 5"
		C942	0CE107CF638	"100UF SHL,SD 16V M FM5 TP 5"
		C943	0CK56101515	560PF D 1KV 10% B(Y5P) TR
		C951	0CE108CF630	"1000UF SHL,SD 16V 20% FM5 BULK"
		C952	0CE107CF638	"100UF SHL,SD 16V M FM5 TP 5"
		C953	0CE107CF638	"100UF SHL,SD 16V M FM5 TP 5"
		C954	0CE108ED618	1000UF KMG 10V M FL TP 5
		C971	0CE476EK638	47UF KMG 50V M FM5 TP 5
		C998	0CE227EL630	220UF KMG 63V 20% FM5 BULK
DIODES				
		ZD301	0DZPT43009A	UZ-4.3BSB PCTRONIX TP52 DO34 500MW 4.3BV 5MA PF
		ZD402	0DZ560009AG	GDZJ5.6B TP GRANDE DO-34 500MW 5.6V 5MA
		ZD403	0DZ560009AG	GDZJ5.6B TP GRANDE DO-34 500MW 5.6V 5MA
		ZD404	0DZ560009AG	GDZJ5.6B TP GRANDE DO-34 500MW 5.6V 5MA
		ZD405	0DZ560009AG	GDZJ5.6B TP GRANDE DO-34 500MW 5.6V 5MA
		ZD406	0DZ560009AG	GDZJ5.6B TP GRANDE DO-34 500MW 5.6V 5MA
		ZD902	0DZ510009BE	GDZ5.1B TP GRANDE DO34 500MW 5.1V 20MA.PF
		D301	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D302	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D303	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D304	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D305	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D306	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D307	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D308	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D309	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D310	0DS124409AA	ISS244 TP ROHM KOREA -----
		D311	0DS124409AA	ISS244 TP ROHM KOREA -----
		D312	0DS124409AA	ISS244 TP ROHM KOREA -----
		D313	0DS124409AA	ISS244 TP ROHM KOREA -----
		D314	0DS124409AA	ISS244 TP ROHM KOREA -----
		D315	0DS124409AA	ISS244 TP ROHM KOREA -----
		D316	0DRTW00119A	1N4005-1021 TIWAN SEMI TP DO41 600V 1A 30A 2USSEC 5.0UA
		D401	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D402	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D403	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D406	0DS124409AA	ISS244 TP ROHM KOREA -----
		D501	0DSGF00019A	1N4148 GULF TP DO35 100V 0.15A 2A 4NSSEC 25UA
		D703	0DRGF00120A	MUR460(15MM) GULF BK DO201AD 600V
CORE&COILS				
			FB302	6210TCE003L
			FB305	BAS3580T BO SUNG 3580MM AXIAL52MM
			FB306	BRS2550B BO SUNG 2550MM RADIAL
			FB307	BAS3580T BO SUNG 3580MM AXIAL52MM
			FB308	B2550T BO SUNG 2550MM AXIAL52MM
			FB309	BAS2550T BO SUNG 2550MM AXIAL52MM
			FB310	BRD3510B BO SUNG 3510MM RADIAL
			FB313	BAS2550T BO SUNG 2550MM AXIAL52MM
			FB701	BAS3580T BO SUNG 3580MM AXIAL52MM

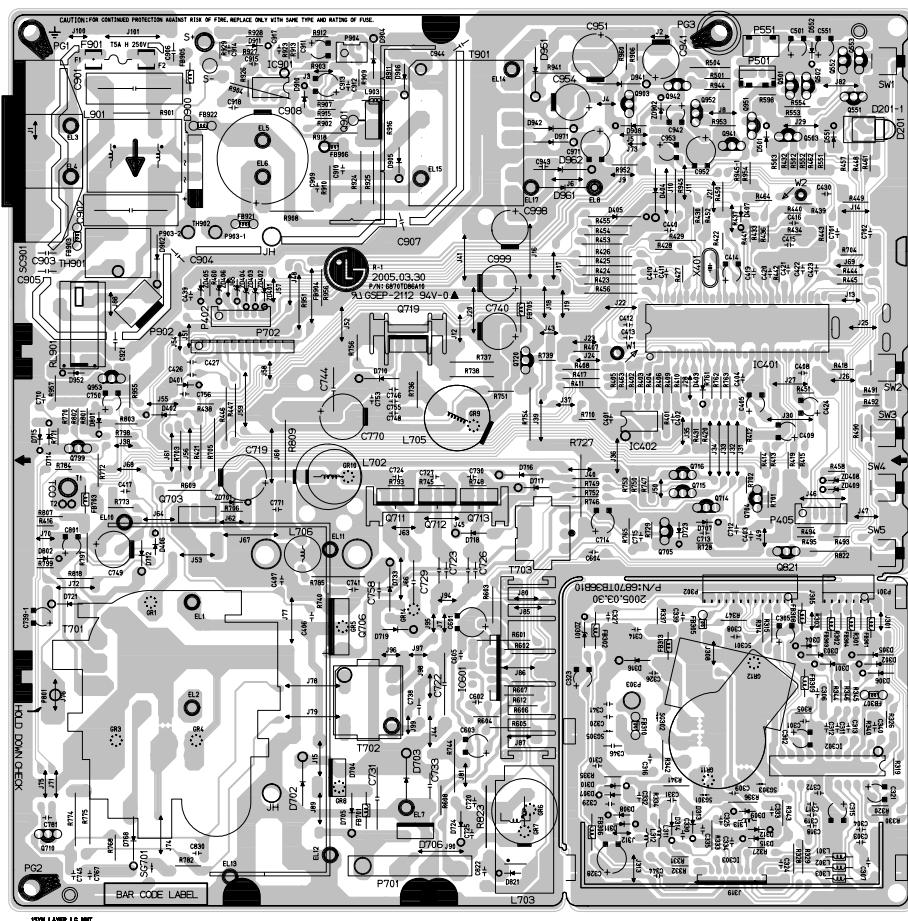
MODEL :505EM				DATE:2005.06.11			
*S	*AL	LOC NO.	PART NO.	DESCRIPTION/SPECIFICATON			
		FB903	6210TCE003P	BRS2550B BO SUNG 2550MM RADIAL	R301	ORD0752Q609	75 1/4W(3 5% TA52
		FB905	6210TCE003J	BAS2550T BO SUNG 2550MM AXIAL52MM	R302	ORD0752Q609	75 1/4W(3 5% TA52
		FB906	6210TCE003P	BRS2550B BO SUNG 2550MM RADIAL	R303	ORD0752Q609	75 1/4W(3 5% TA52
		FB921	6210TCE003A	BRD3510B BO SUNG 3510MM RADIAL	R305	ORN6201F409	6.2K OHM 1/6 W 1.00% TA52
		FB922	6210TCE003A	BRD3510B BO SUNG 3510MM RADIAL	R314	ORD1000Q609	100 1/4W(3 5% TA52
		L903	6210TCE003K	BAS3550T BO SUNG 3550MM AXIAL52MM	R315	ORD1000Q609	100 1/4W(3 5% TA52
		L702	6140TBZ025D	"- H-SIZE,DR12*20-C6.0,150UH 700BJ"	R319	ORD4701Q609	4.70K 1/4W(3 5% TA52
		L703	6140TYZ010J	14*5T 12UH 0.12*30MM 23.5T	R320	ORD4701Q609	4.70K 1/4W(3 5% TA52
		L705	6140TBZ026C	DR15*18-C9.8 100UH 0.1*30MM 40.5T D/D CHOKE	R326	ORD2201Q609	2.20K 1/4W(3 5% TA52
Ics				R327	ORD1001Q609	1K OHM 1/4 W(3.4) 5.00% TA52	
		IC302	0IPRPNS025C	"LM1246DDC/NA,NOPB NATIONAL SEMICONDUCTOR 24,DIP ST LF,ONE CHIP (VIDEO+OSD)"	R328	ORD1001Q609	1K OHM 1/4 W(3.4) 5.00% TA52
		IC303	0IPRP00543A	LM2476 NATIONAL SEMICONDUCTOR T0-247 ST MONOLITHIC 3CH 6NS CRT DRIVE&BIAS CLAMP	R329	ORD1001Q609	1K OHM 1/4 W(3.4) 5.00% TA52
		IC401	0IMCRPH033B	LGM41B-040/CJH PHILIPS 56 SDIP ST DEFLECTION & MICOM(L4-CDT)	R330	ORD1001Q609	1K OHM 1/4 W(3.4) 5.00% TA52
		IC402	0ISS524808B	"S524A60X81-DCB0,LF SAMSUNG ELECTRONICS 8DIP ST 8K EEPROM"	R331	ORD2400Q609	240 OHM 1/4 W (3.4) 5% TA52
		IC601	0IPRPPH018A	"TDA4867J PHILIPS 9PIN,ST DIP VERTICAL OUTPUT IC"	R332	ORD2400Q609	240 OHM 1/4 W (3.4) 5% TA52
		IC901	0ISS384200A	KA3842B (PWM)	R333	ORD2400Q609	240 OHM 1/4 W (3.4) 5% TA52
TRANSISTORs				R334	ORD3303Q609	330K 1/4W(3 5% TA52	
		Q501	0TR320209AA	KTC3202-Y TP KEC TO92 (KTC1959) NPN	R335	ORD3303Q609	330K 1/4W(3 5% TA52
		Q502	0TR127009AA	KTA1270-Y(KTA562TM) TP KEC TO92 PNP	R336	ORD3303Q609	330K 1/4W(3 5% TA52
		Q503	0TRAU80031A	2SC5343YAT(C3198) AUK KOREA R/TP TO92 60V 150MA	R337	ORD1000Q609	100 1/4W(3 5% TA52
		Q703	0TFFC10012A	FQPF10N20C FAIRCHILD ST TO220F 200V 9.5A	R338	ORD0102Q609	10 1/4W(3 5% TA52
		Q704	0TR390409CA	FAIRCHILD 2N3904(TA) TP TO-92 60V 0.2A	R340	ORD1002F409	10K OHM 1/6 W 1.00% TA52
		Q705	0TR200009AB	"KTC200-Y,TP,KEC"	R341	ORD0332A609	33 OHM 1/2 W(7.0) 5.00% TA52
		Q706	0TRFC10011B	FJAF6810A FAIRCHILD ST TO3PF 1550V 10A/20A	R342	ORD0332A609	33 OHM 1/2 W(7.0) 5.00% TA52
		Q711	0TFFC10012A	FQPF10N20C FAIRCHILD ST TO220F 200V 9.5A	R343	ORD0332A609	33 OHM 1/2 W(7.0) 5.00% TA52
		Q713	0TFFC10012A	FQPF10N20C FAIRCHILD ST TO220F 200V 9.5A	R344	ORD0332Q609	33 1/4W(3 5% TA52
		Q715	0TRAU80031A	2SC5343YAT(C3198) AUK KOREA R/TP TO92 60V 150MA	R345	ORD0332Q609	33 1/4W(3 5% TA52
		Q716	0TRAU80031A	2SC5343YAT(C3198) AUK KOREA R/TP TO92 60V 150MA	R346	ORD0332Q609	33 1/4W(3 5% TA52
		Q719	0TFFC10012A	FQPF10N20C FAIRCHILD ST TO220F 200V 9.5A	R347	ORD0202Q609	20 1/4W(3 5% TA52
		Q720	0TR390409CA	FAIRCHILD 2N3904(TA) TP TO-92 60V 0.2A	R401	ORD2200Q609	220 OHM 1/4 W(3.4) 5.00% TA52
		Q799	0TRAU80036A	SPS92AT AUK KOREA R/TP TO92 -300V - 500MA	R402	ORD1000Q609	100 1/4W(3 5% TA52
		Q901	0TF760000AD	SSS7N60B FAIRCHILD ST TO220F 650V 7A	R403	ORD1000Q609	100 1/4W(3 5% TA52
		Q903	0TR100809AA	KSC1008C-Y TP SAMSUNG TO92 NPN	R404	ORD1000Q609	100 1/4W(3 5% TA52
		Q941	0TRAU80031A	2SC5343YAT(C3198) AUK KOREA R/TP TO92 60V 150MA	R405	ORD2201Q609	2.20K 1/4W(3 5% TA52
		Q942	0TRAU80034A	STB1277LAT(B1273) AUK KOREA R/TP TO-92L -30V -2A	R406	ORD2201Q609	2.20K 1/4W(3 5% TA52
		Q951	0TRAU80031A	2SC5343YAT(C3198) AUK KOREA R/TP TO92 60V 150MA	R407	ORD4701Q609	4.70K 1/4W(3 5% TA52
		Q952	0TRAU80034A	STB1277LAT(B1273) AUK KOREA R/TP TO-92L -30V -2A	R408	ORD1000Q609	100 1/4W(3 5% TA52
		Q953	0TRAU80031A	2SC5343YAT(C3198) AUK KOREA R/TP TO92 60V 150MA	R409	ORD1000Q609	100 1/4W(3 5% TA52
RESISTORs				R411	ORD1000Q609	100 1/4W(3 5% TA52	
		L301	0RD0822Q609	82 1/4W(3 5% TA52	R412	ORD1000Q609	100 1/4W(3 5% TA52
		L302	0RD0822Q609	82 1/4W(3 5% TA52	R413	ORD1000Q609	100 1/4W(3 5% TA52
		L303	0RD0822Q609	82 1/4W(3 5% TA52	R414	ORD1602Q609	16K OHM 1/4 W(3.4) 5.00% TA52
				R416	ORN1501F409	1.5K OHM 1/6 W 1.00% TA52	
				R417	ORD1000Q609	100 1/4W(3 5% TA52	
				R418	ORD0912Q609	91 OHM 1/4 W (3.4) 5% TA52	
				R419	ORN4702F409	47K OHM 1/6 W 1.00% TA52	
				R420	ORD2001Q609	2K OHM 1/4 W(3.4) 5.00% TA52	
				R421	ORD1501Q609	1.50K 1/4W(3 5% TA52	
				R422	ORD2001Q609	2K OHM 1/4 W(3.4) 5.00% TA52	
				R423	ORD1000Q609	100 1/4W(3 5% TA52	
				R424	ORD1000Q609	100 1/4W(3 5% TA52	
				R425	ORD1000Q609	100 1/4W(3 5% TA52	
				R426	ORD1000Q609	100 1/4W(3 5% TA52	
				R427	ORD1002Q609	10K OHM 1/4 W(3.4) 5.00% TA52	
				R429	ORD1002Q609	10K OHM 1/4 W(3.4) 5.00% TA52	
				R430	ORD1000Q609	100 1/4W(3 5% TA52	
				R431	ORD1802Q609	18K OHM 1/4 W(3.4) 5.00% TA52	
				R432	ORD2001Q609	2K OHM 1/4 W(3.4) 5.00% TA52	
				R433	ORD2001Q609	2K OHM 1/4 W(3.4) 5.00% TA52	
				R434	ORD7502Q609	75K OHM 1/4 W(3.4) 5.00% TA52	
				R436	ORD3601Q609	3.60K 1/4W(3 5% TA52	
				R437	ORN2702G409	27K OHM 1/4 W 1.00% TA52	
				R438	ORD1303Q609	130K 1/4W(3 5% TA52	
				R439	ORN5600F409	560 1/6W 1% TA52	
				R440	ORN1001F409	1K OHM 1/6 W 1.00% TA52	

MODEL :505EM				DATE:2005.06.11
*S	*AL	LOC NO.	PART NO.	DESCRIPTION/SPECIFICATON
		T703	6170TCZ015A	15""" "EI-19 4.45MH H-DRIVE,700BJ"
⚠		T901	6170TMZ153A	EER3435 300UH V-16PIN T710BL SI/SC/NY/J/S /TC 71-85KHZ
⚠		TH901	163-053D	J502P62C090Q290 JAHWA +/-20 220Vrms
		TH902	6322A00005A	SCK-083 THINKING 80HM 15% 3A
		X401	6212AA2004L	HC-49U TXC 48MHZ +/- 20 PPM 22PF BULK DIP

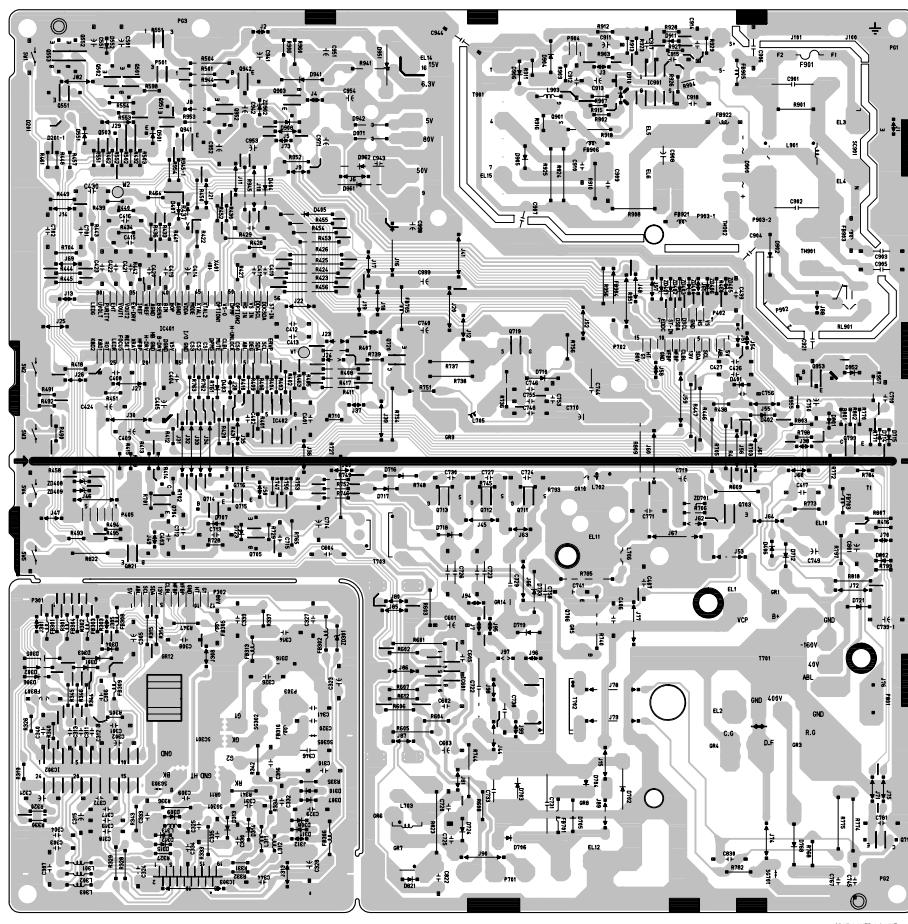


PRINTED CIRCUIT BOARD

1. MAIN BOARD (Component Side)



2. MAIN BOARD (Solder Side)





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